

Chapter 9

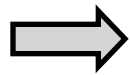
Energy Dispersive X-ray spectrometer:
The Introduction and Application

(Chapter 32, 33)

9.1

X-ray analysis: Why bother?

AEM: analytical electron microscope



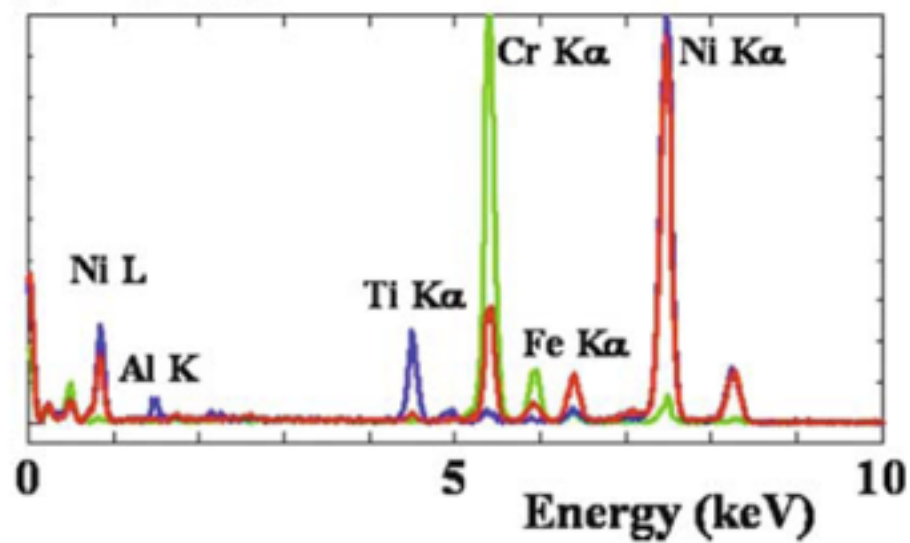
EDX: X-ray energy-dispersive spectrometer

Why bother?

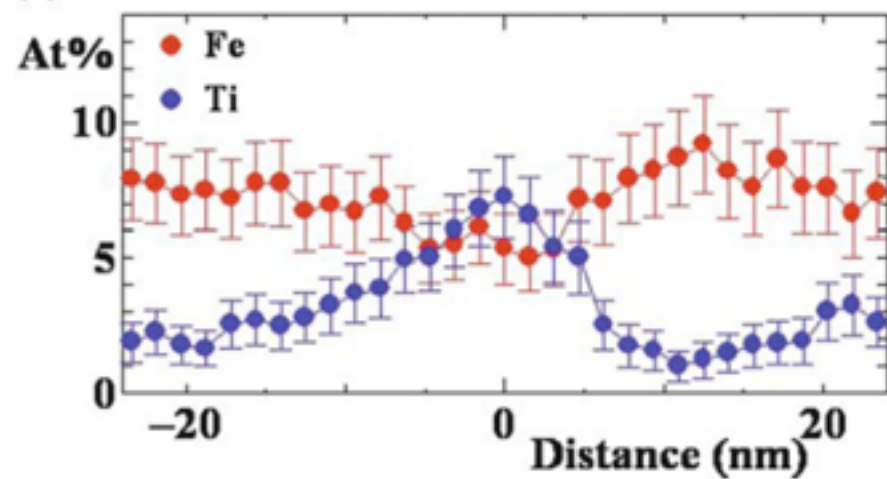
TEM gives us two-dimensional projected images of 3D transparent specimens.

The operator need substantial experience in order to interpret the images correctly.

(A) Counts



(D)

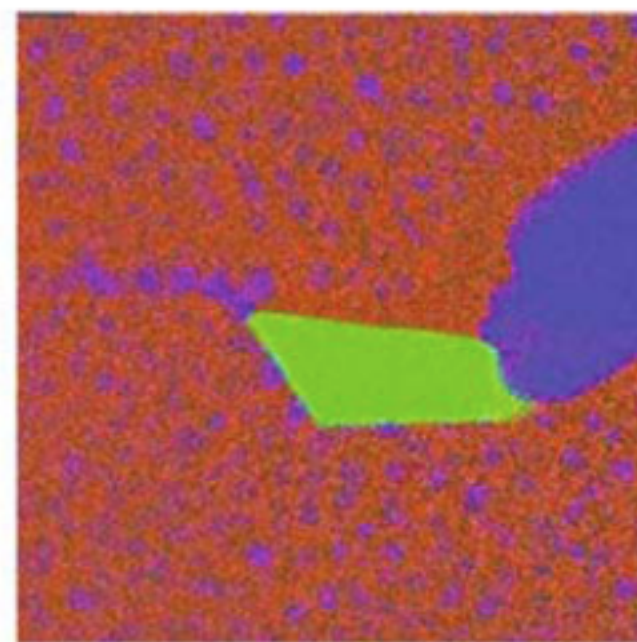


(B)



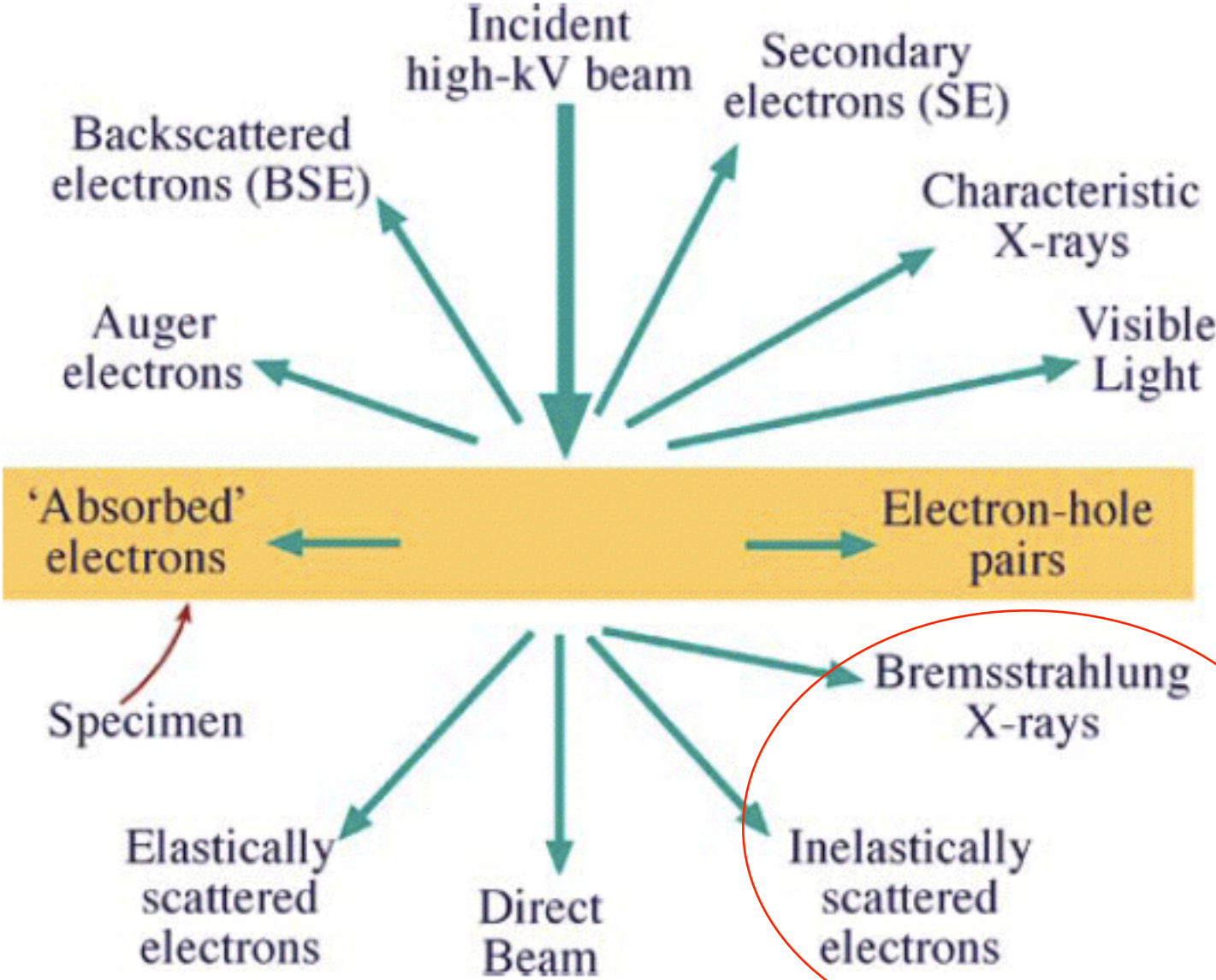
100 nm

(C)



Fe Cr Ti

9.2 TEM beam-specimen interactions and signals



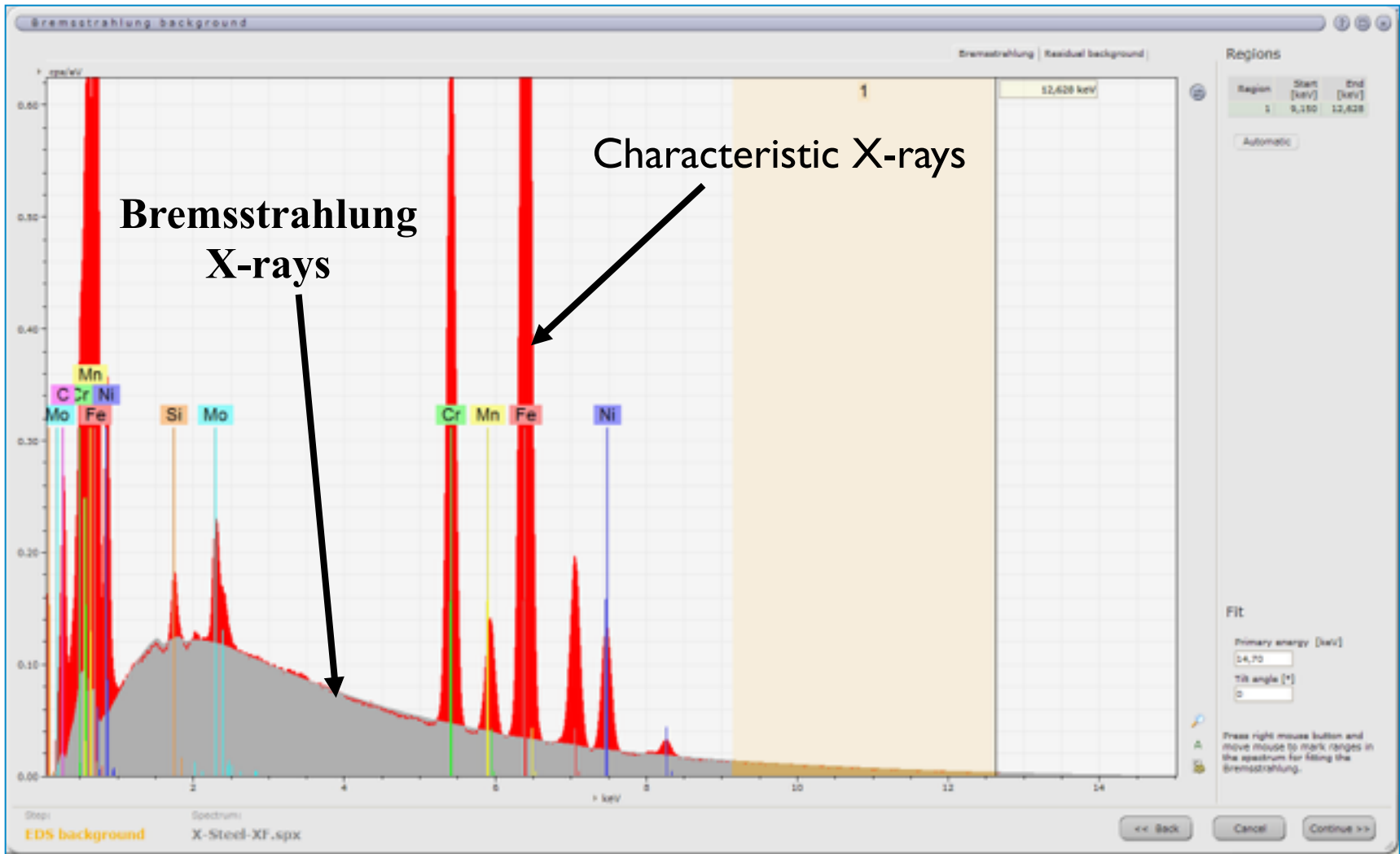
X-RAY EMISSION

What we get from X-ray?

- Element constitute
- Quantify the amount of element

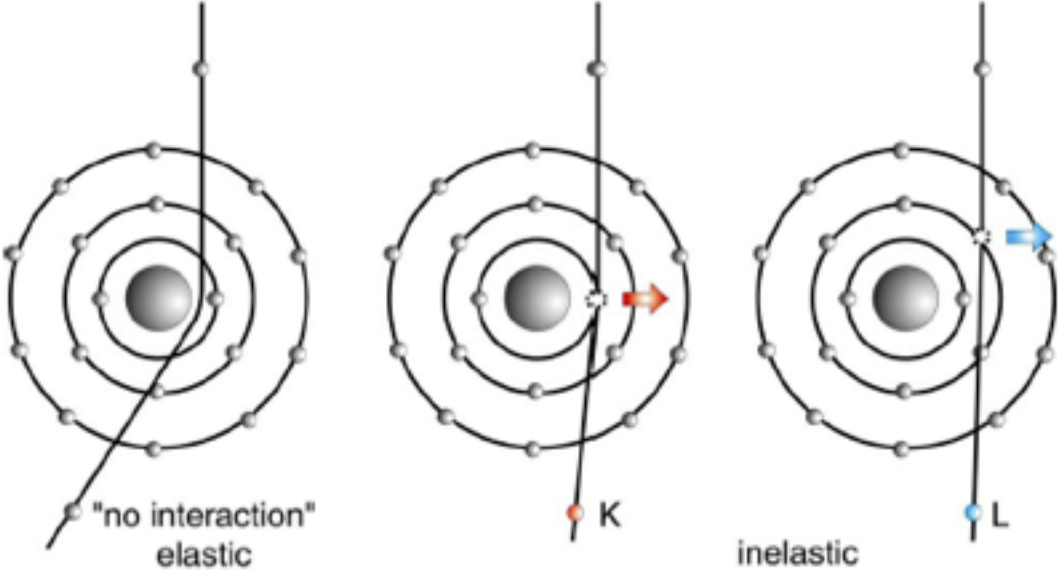
Two kinds of X-rays are produced:

- Characteristic X-rays: useful to the materials scientist
 - Bremsstrahlung X-rays: useful to the biologist
 - electron decelerated by the Coulomb field of the nucleus, it emits Bremsstrahlung X-ray.

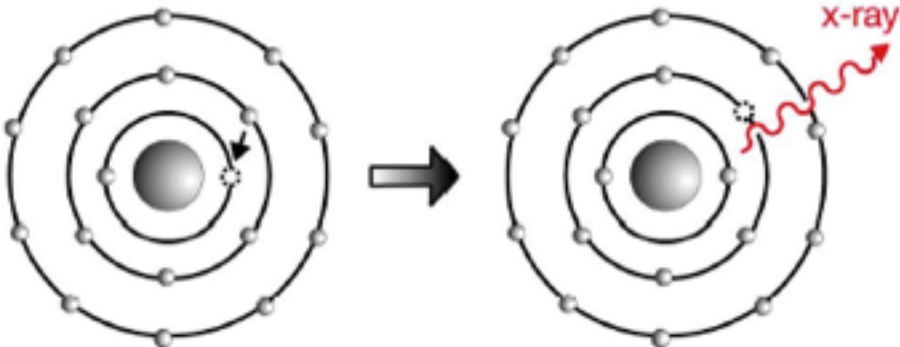


EELS and x-Ray Signal Generation

EELS signal generation

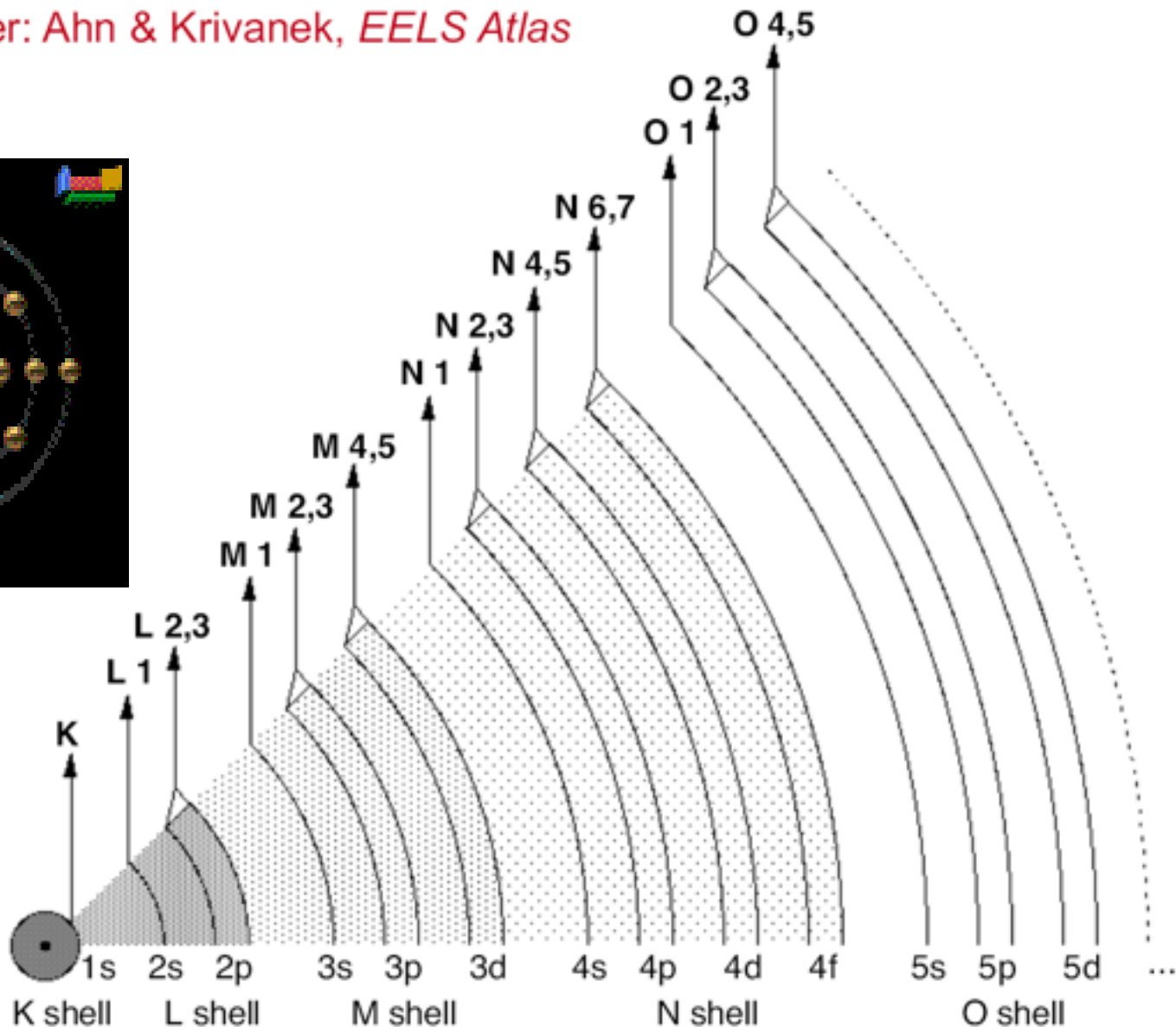
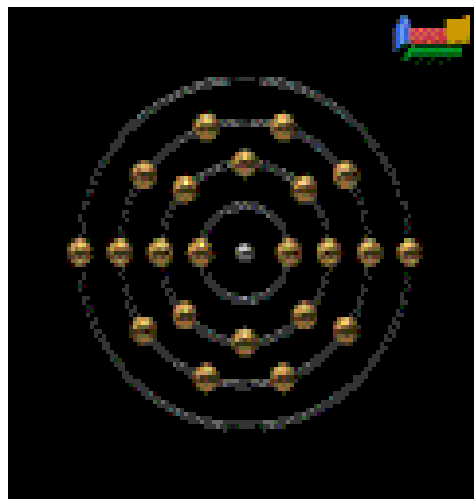


X-ray signal generation



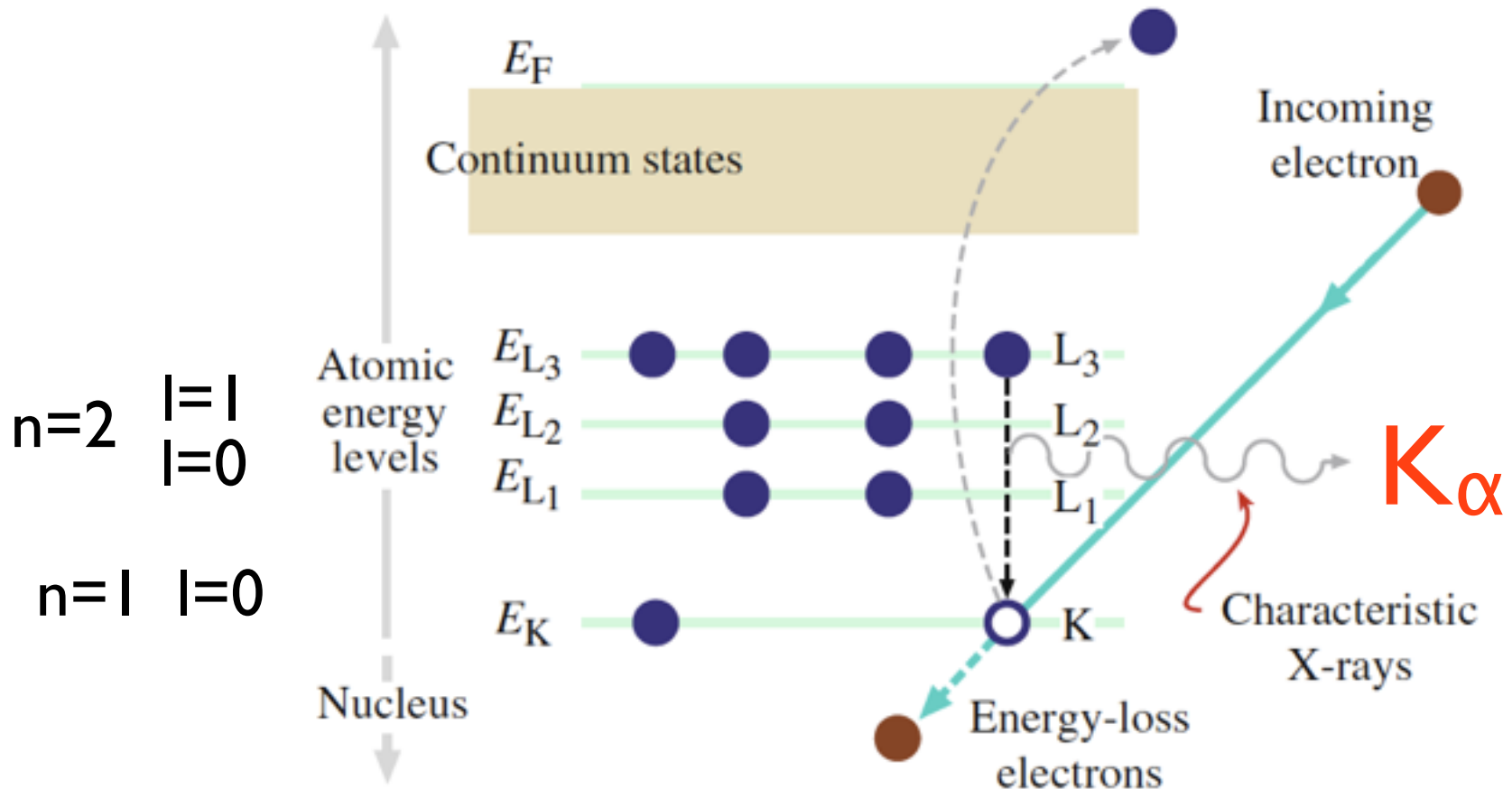
Nomenclature of EELS ionization edges

After: Ahn & Krivanek, *EELS Atlas*



CHARACTERISTIC X-RAYS

How to produce characteristic X-rays?



What are they "characteristic"?

The energy of the emission is characteristic of the difference in energy of the two shells involved and is unique to the atom.

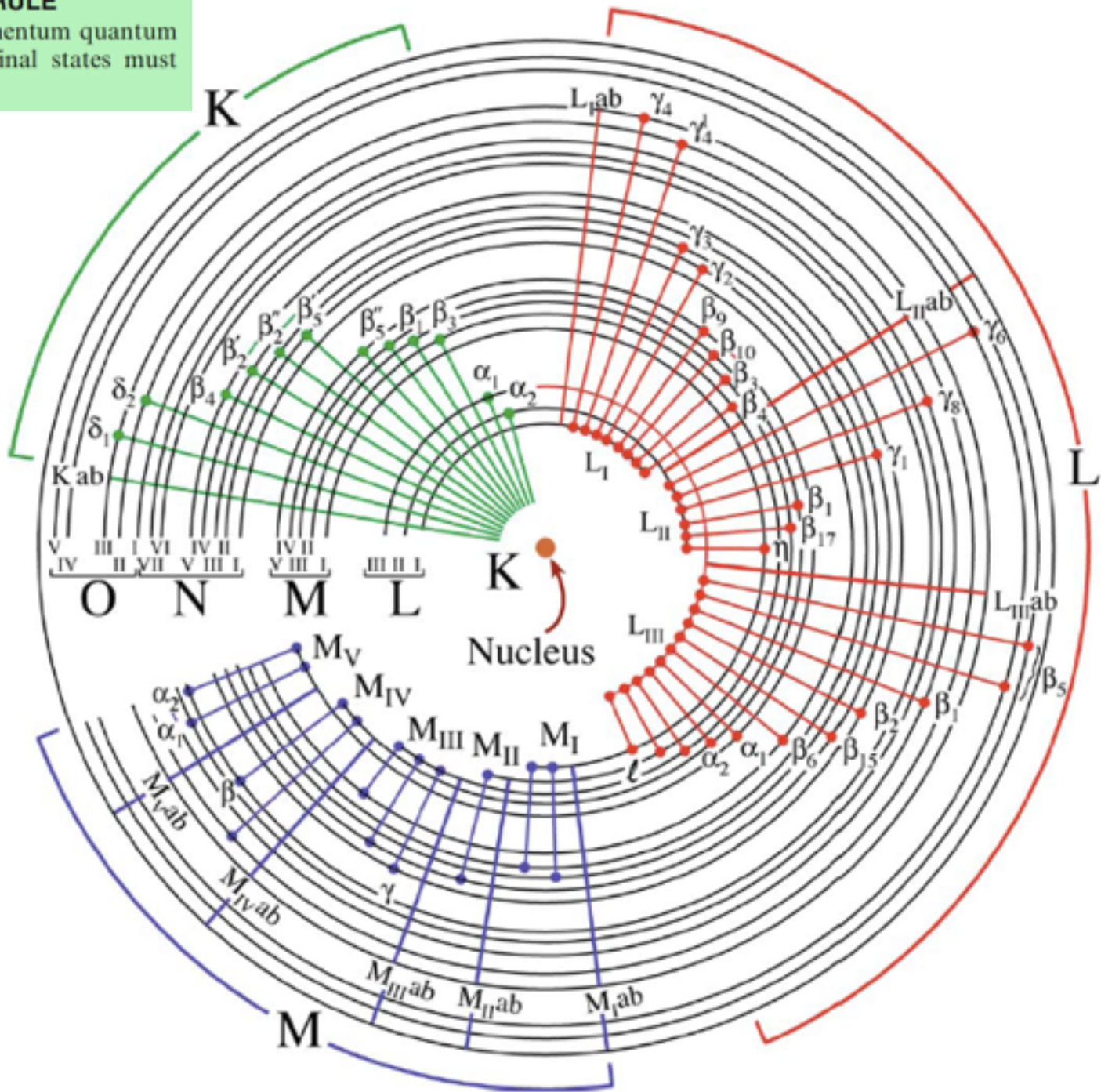
DIPOLE-SELECTION RULE

The change Δl in the angular momentum quantum number between the initial and final states must equal ± 1 .

Electrons must obey
when they jumped
between shells



$$\Delta l = \pm 1, \Delta m_l = \pm 1, 0$$



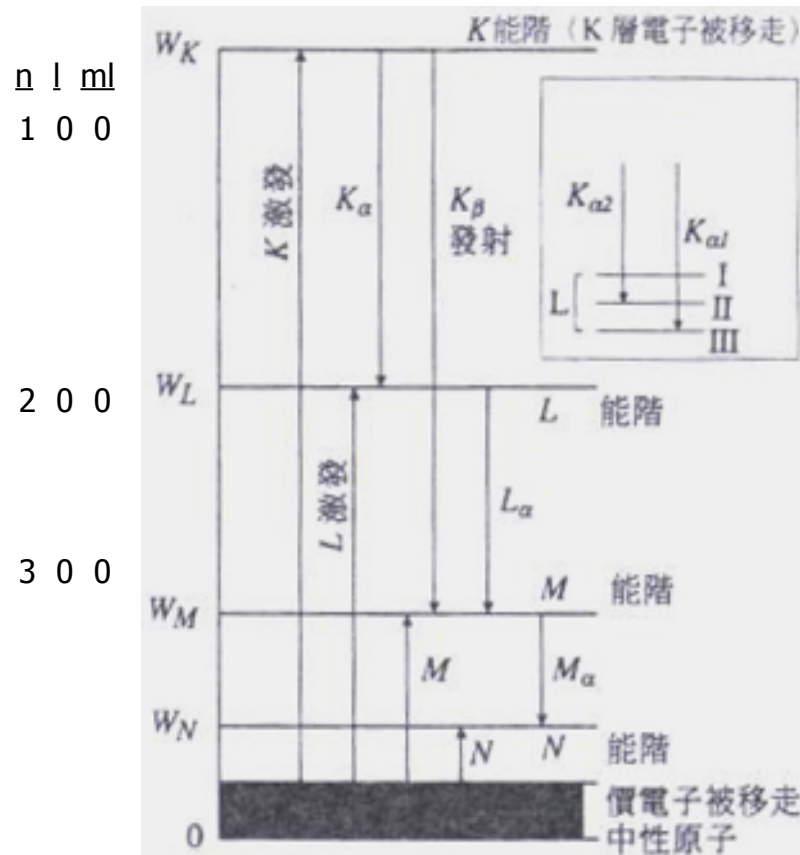
Selection rule:

ELECTRON SHELLS

Electrons must obey when they jumped between shells



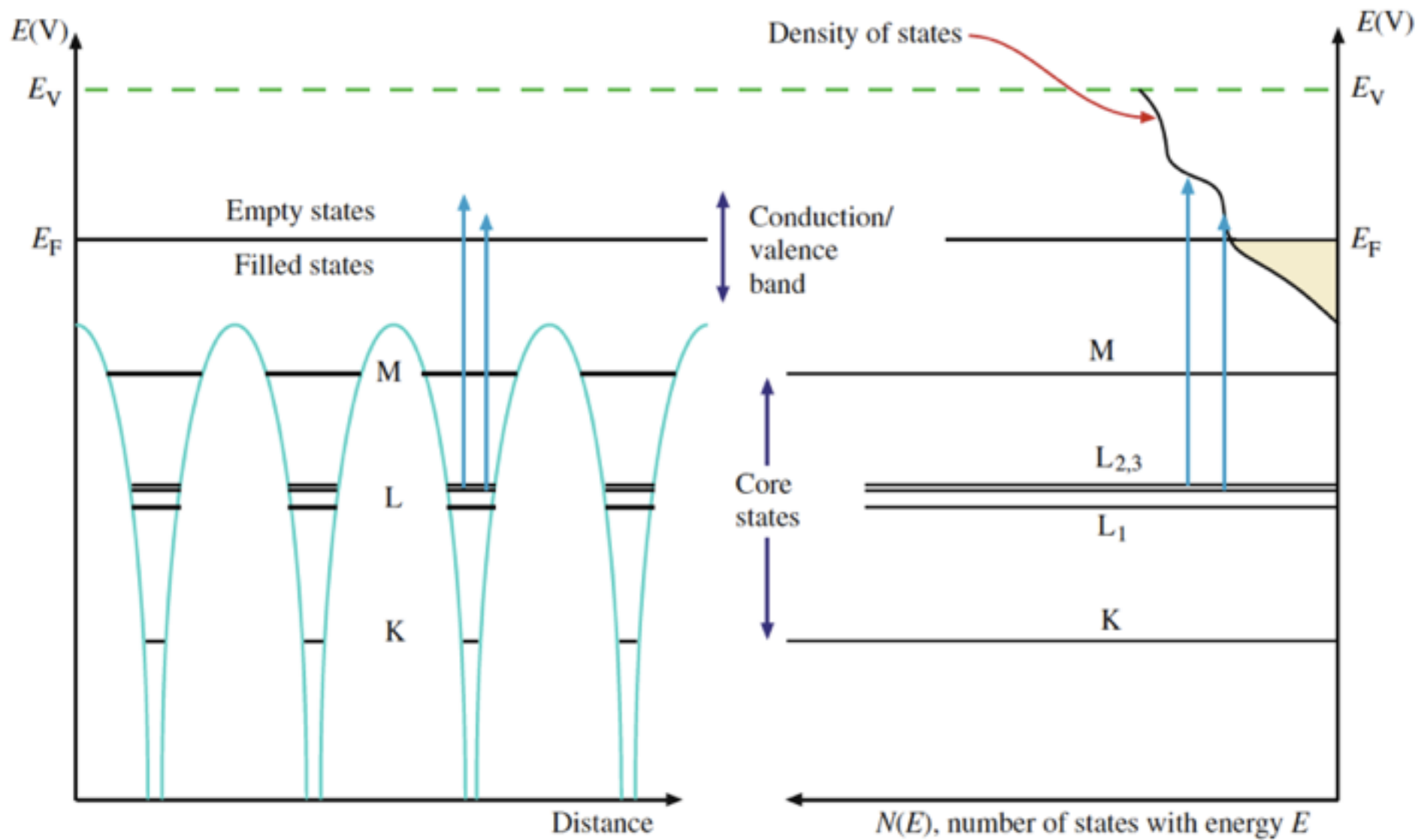
$$\Delta l = \pm 1, \Delta m_l = \pm 1, 0$$

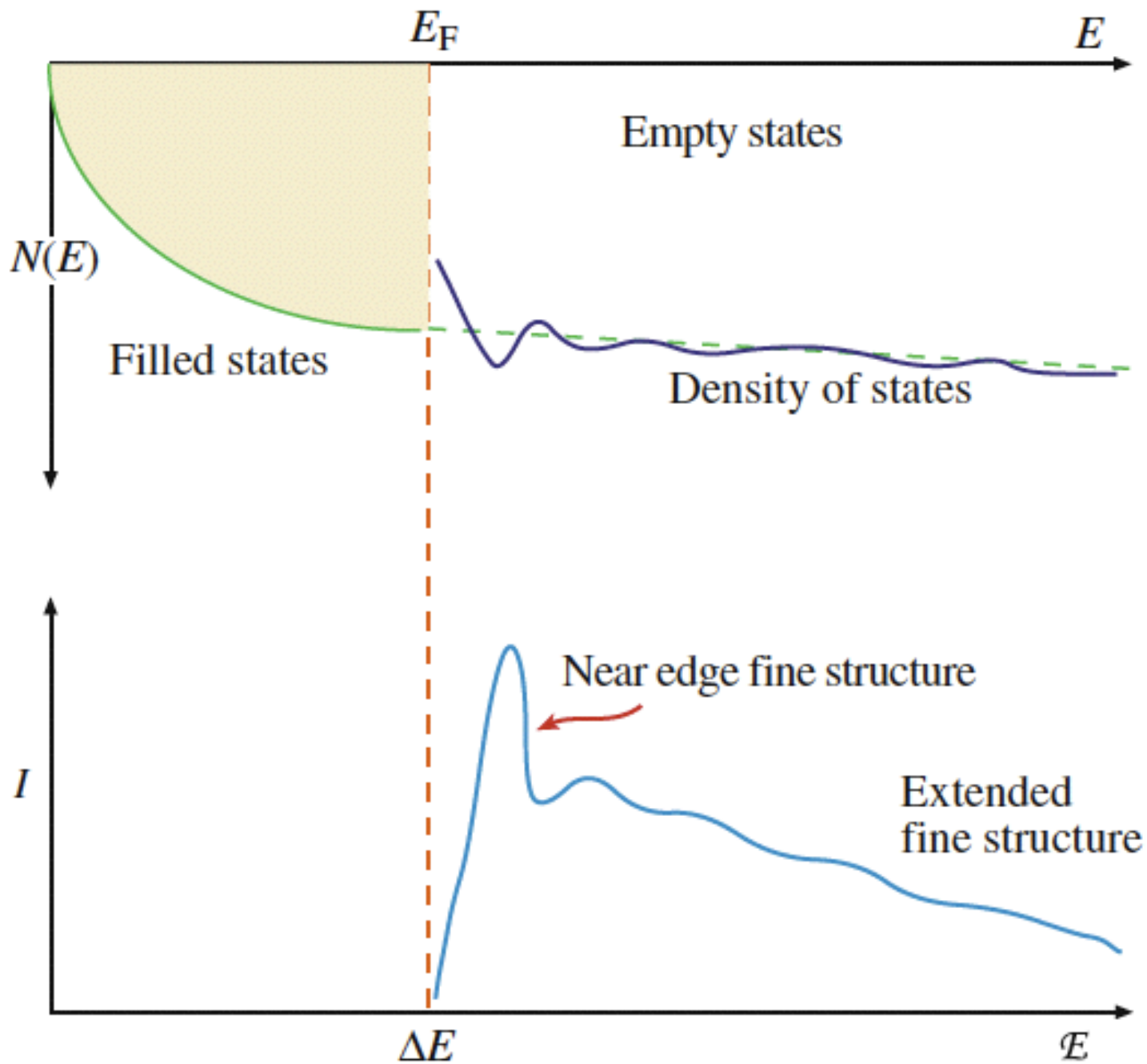


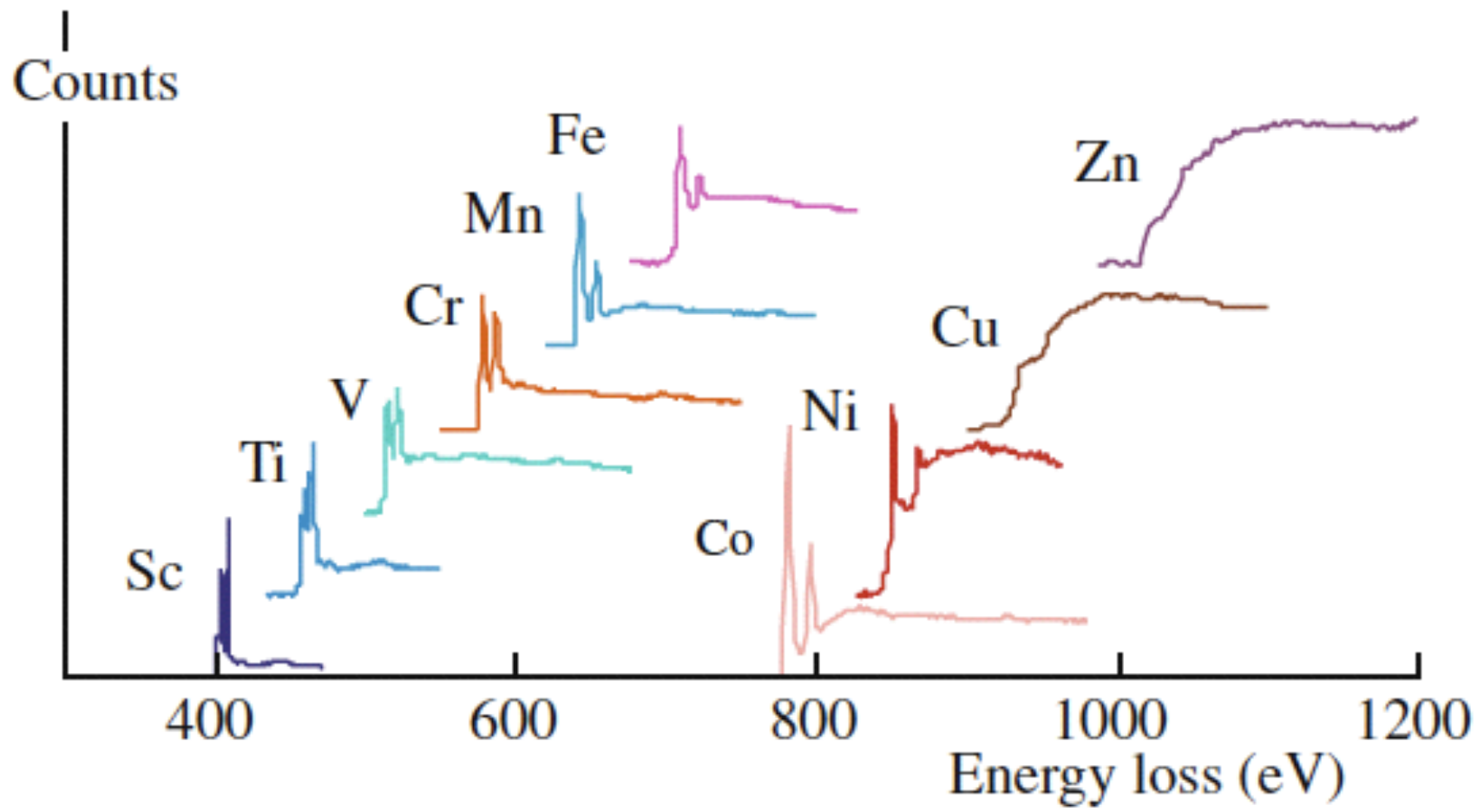
n	l	m_l
1	0	0
2	0	0
2	1	0
2	1	± 1

DIPOLE-SELECTION RULE

The change Δl in the angular momentum quantum number between the initial and final states must equal ± 1 .

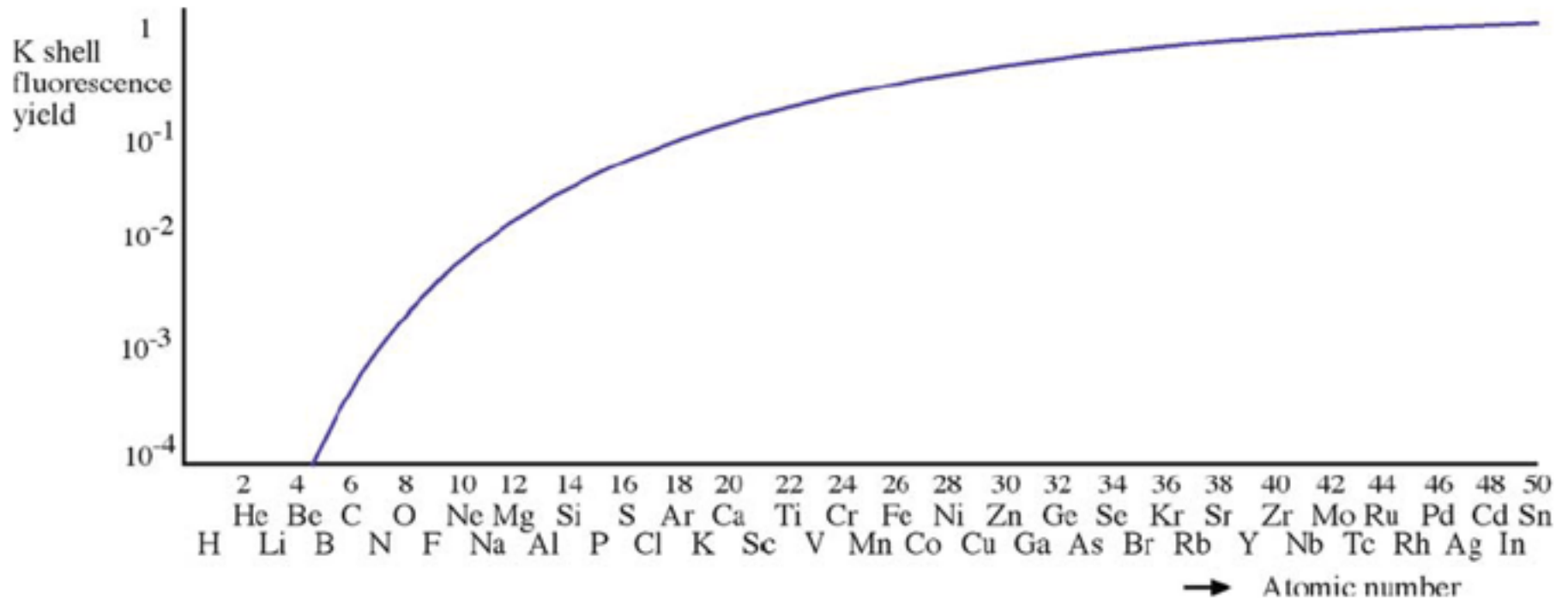






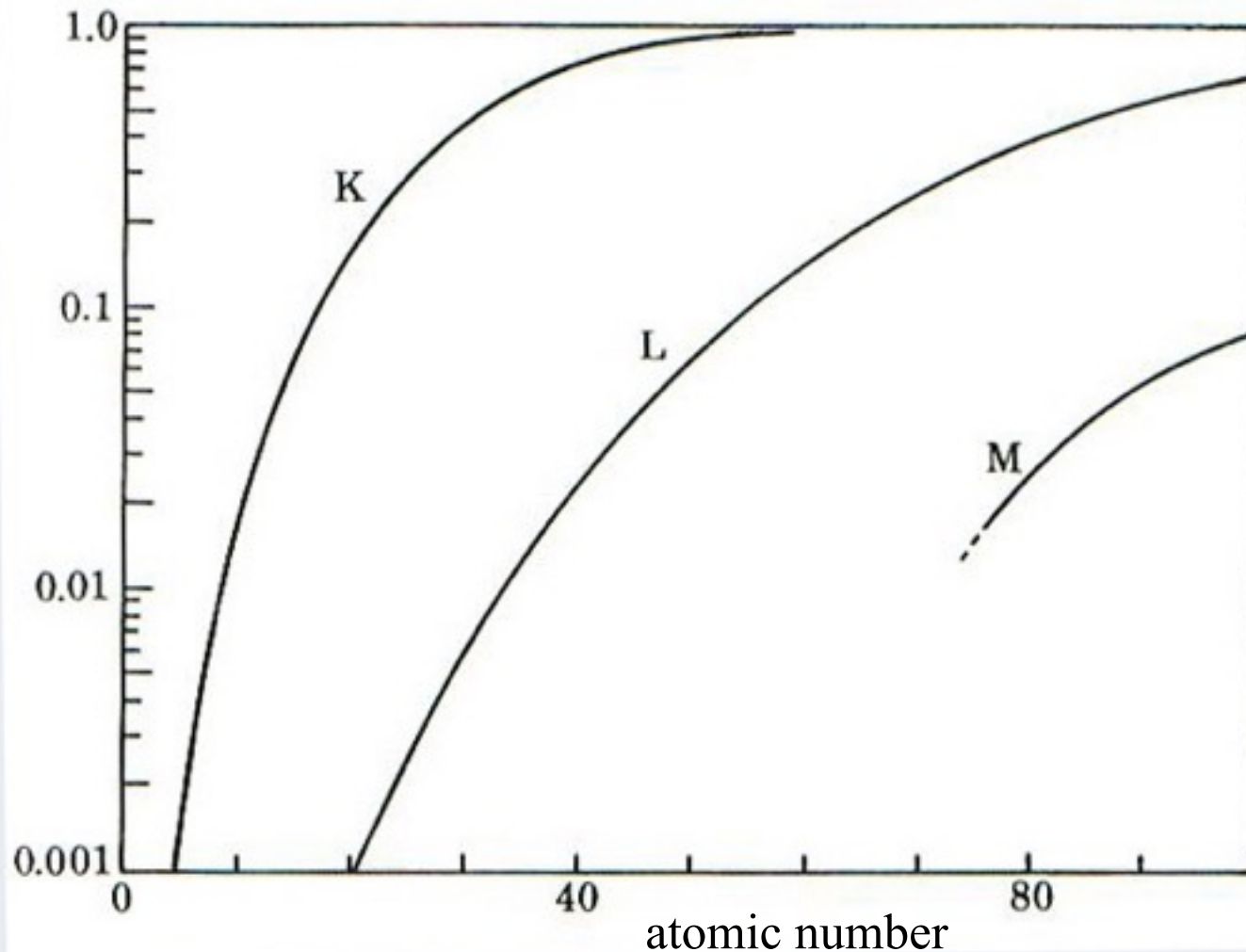
X-ray fluorescence yield

$$\omega = \frac{Z^4}{a + Z^4}$$



X-ray fluorescence yield (log scale) as a function of atomic number

Yield is very low for low z elements



9.3 EDX vs EELS

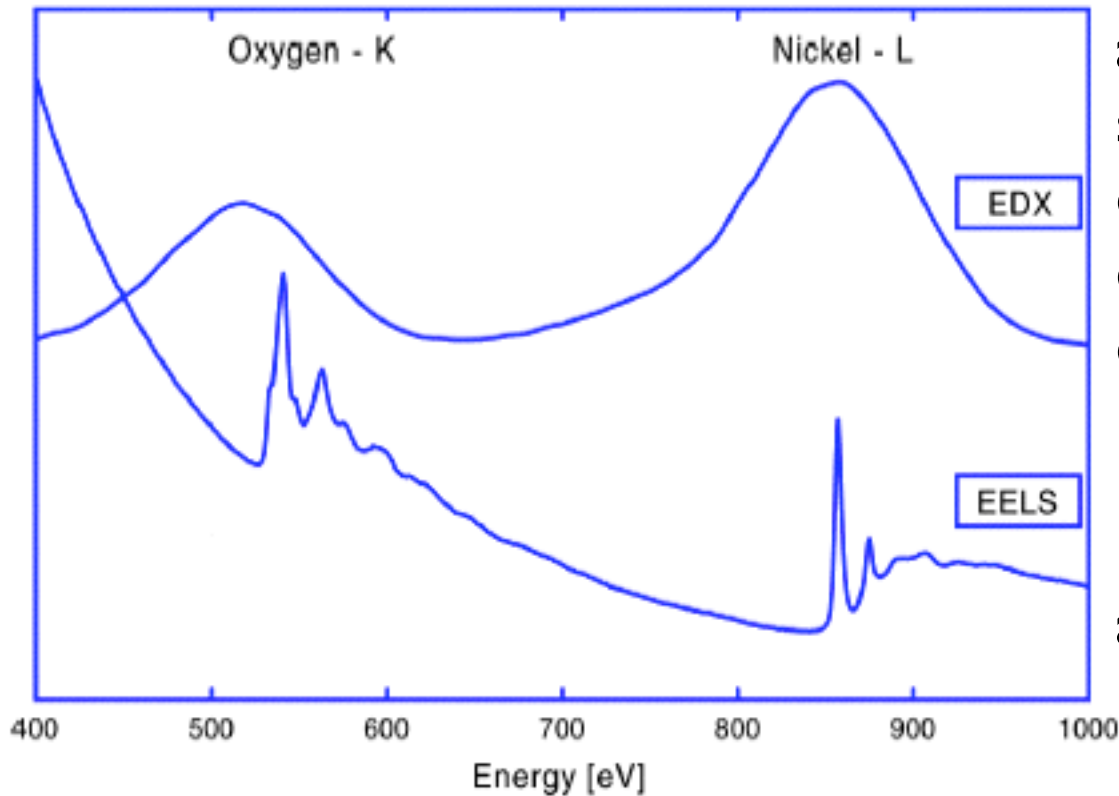
- The *EELS* is one step signal, while *EDX* is a two step signal (low x-ray fluorescence yield for low Z). In general, the yield rate of the EELS is higher than EDX.
- the signal of EELS concentrates in a small angle range of the transmitted beam, but the EDX signal spans around larger angle range.

(a) These two cause EELS has higher core loss
signal

(higher Signal to noise ratio, EELS has less recording
time)

X-ray and EELS spectra

(b) EDX has better Signal/ background ratio



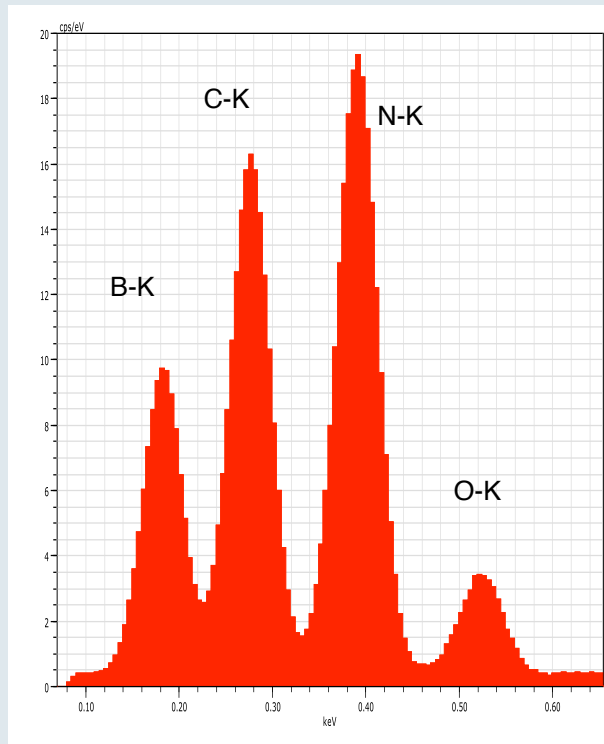
Background of EELS:
arises from the inelastic scattering from the atomic electron whose binding energy less than the edge energy

Background of EDX:
arises from bremsstrahlung

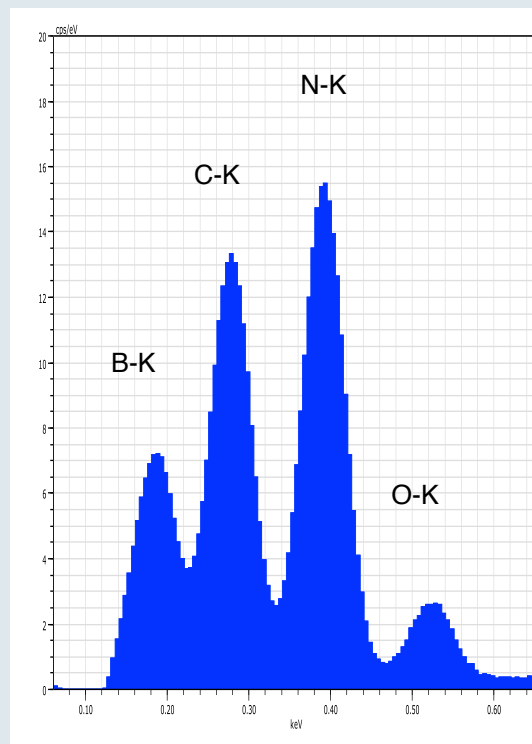
Influence by Resolution changing @ different ICR



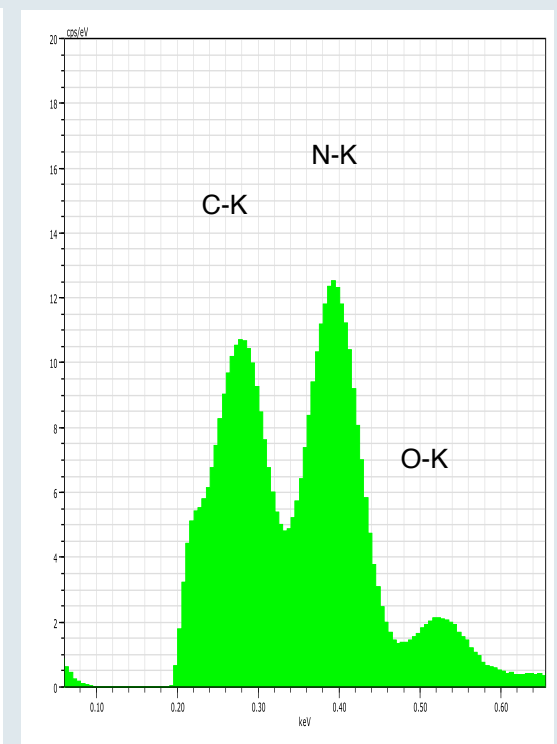
125eV

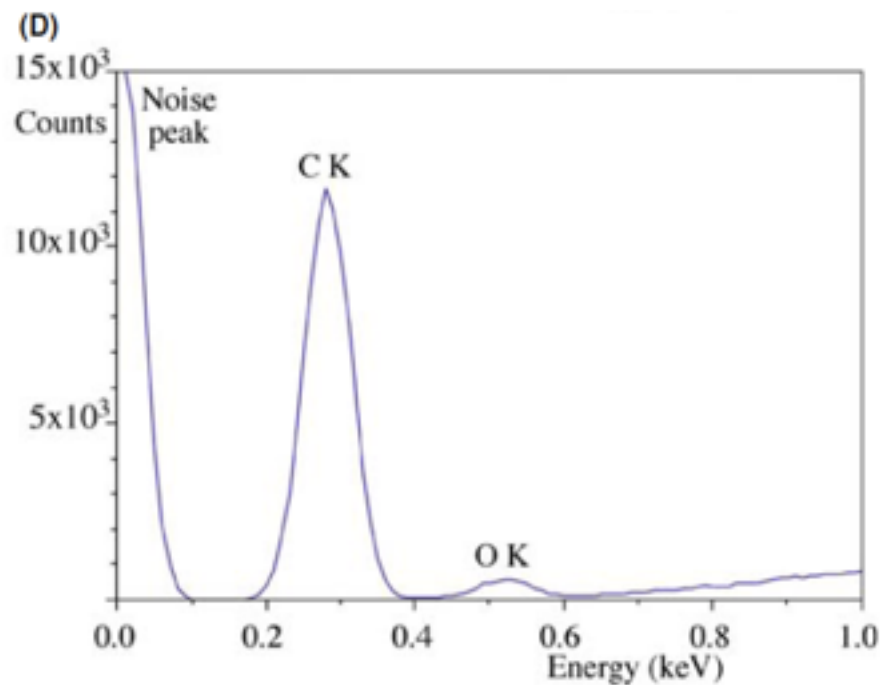
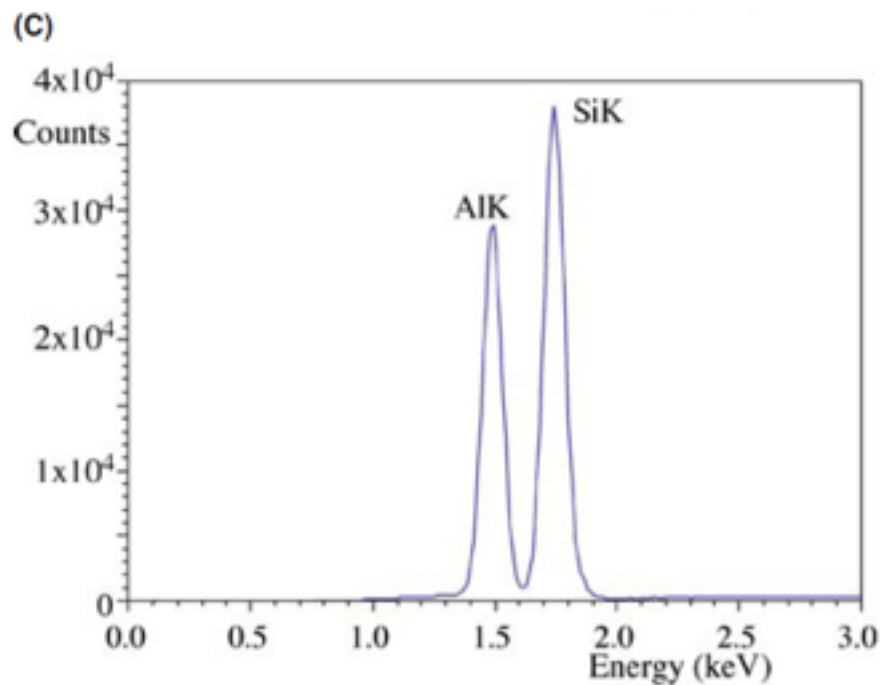
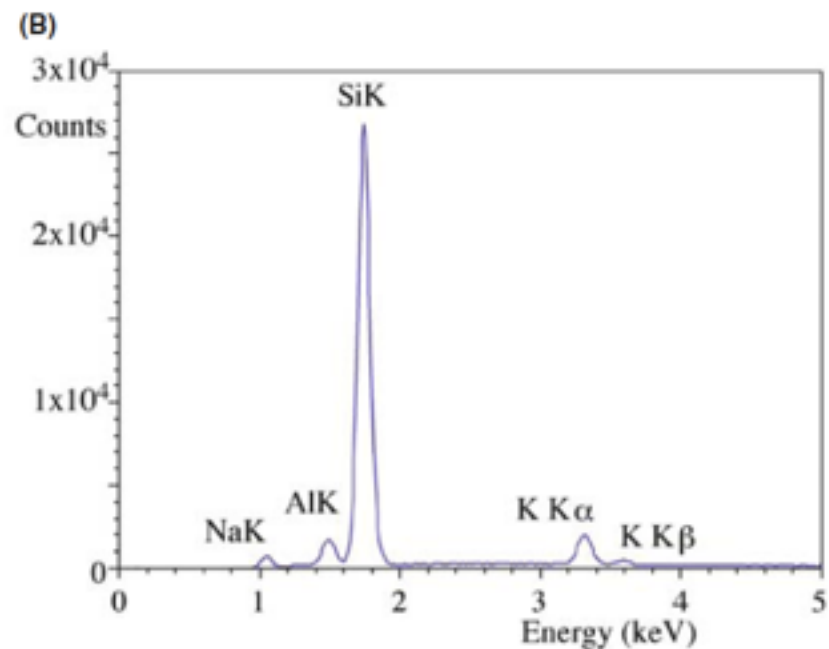
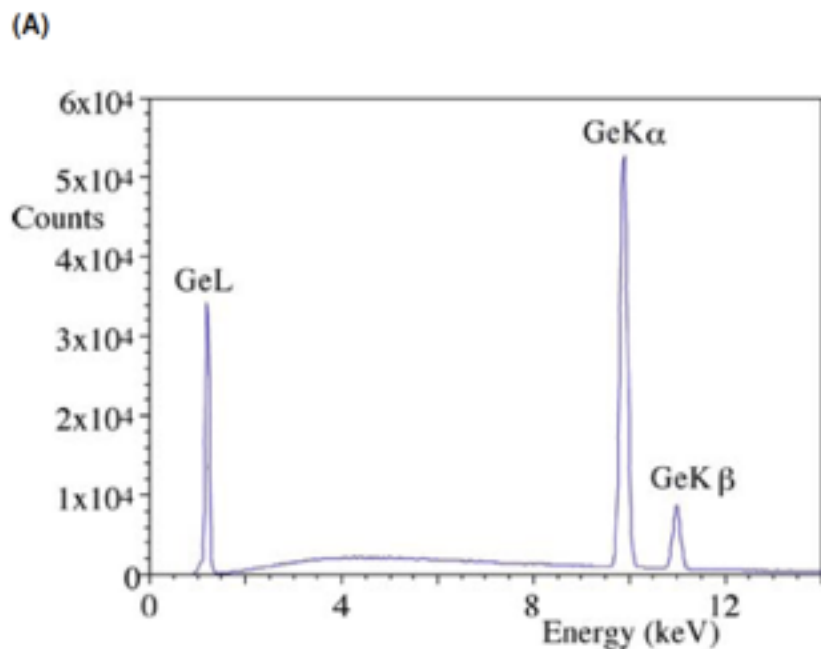


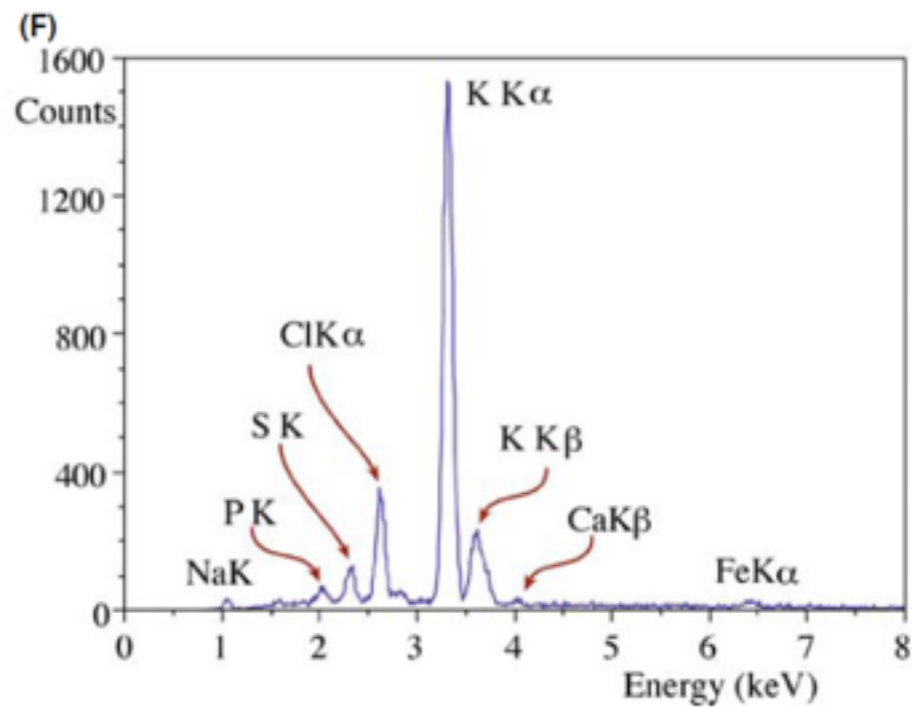
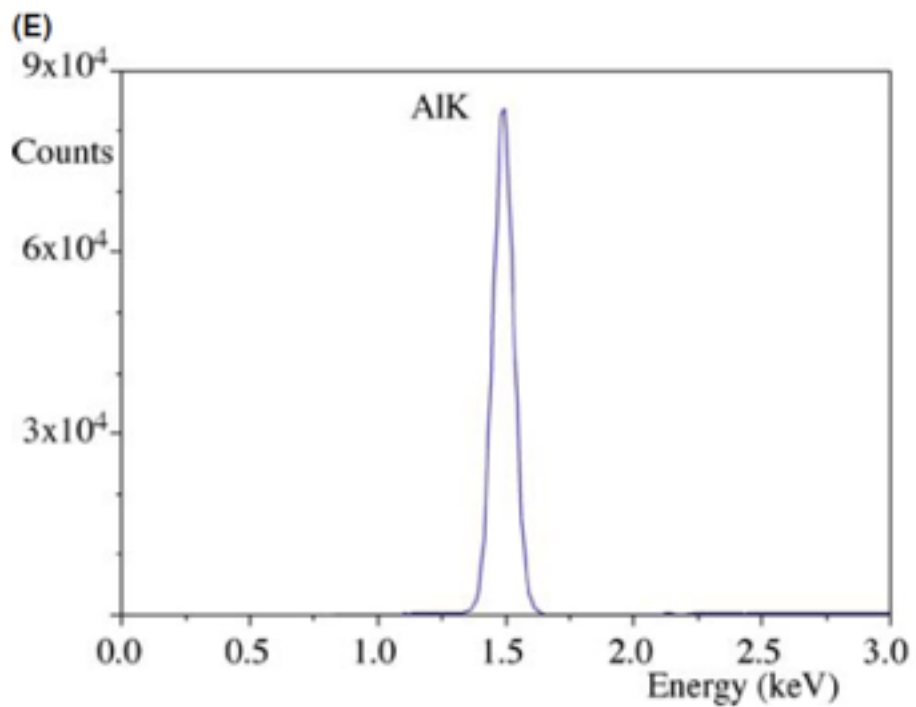
133eV



140eV







9.4

The Energy-Dispersive Spectrometer

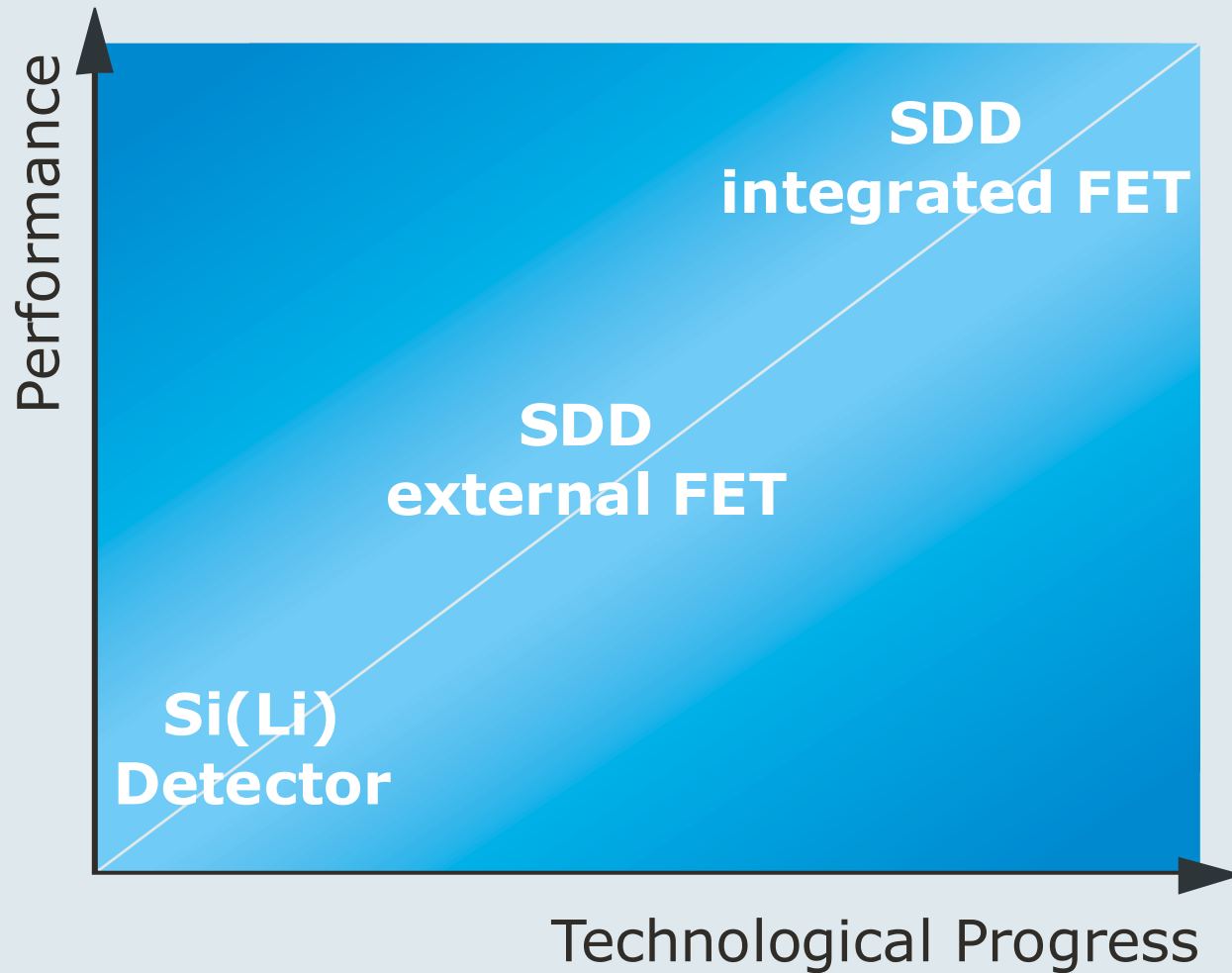
3 COMPONENTS

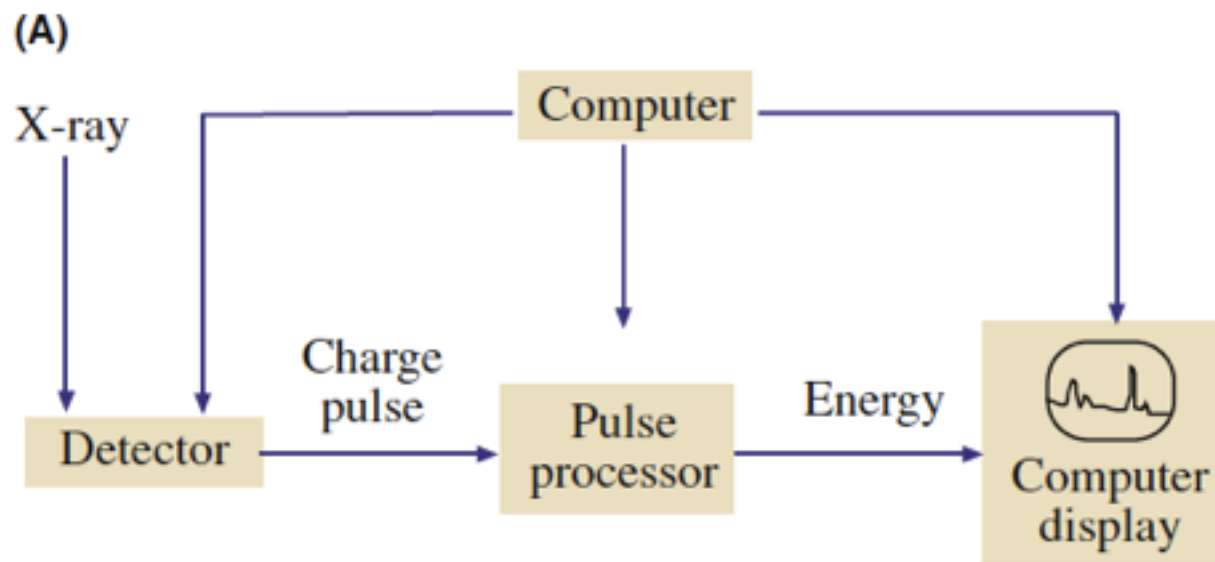
The three main parts of an XEDS system are

- (i) the detector
- (ii) the processing electronics
- (iii) the computer

Si(Li) detector and SDD (Silicon Drift Diode)

Detector Types

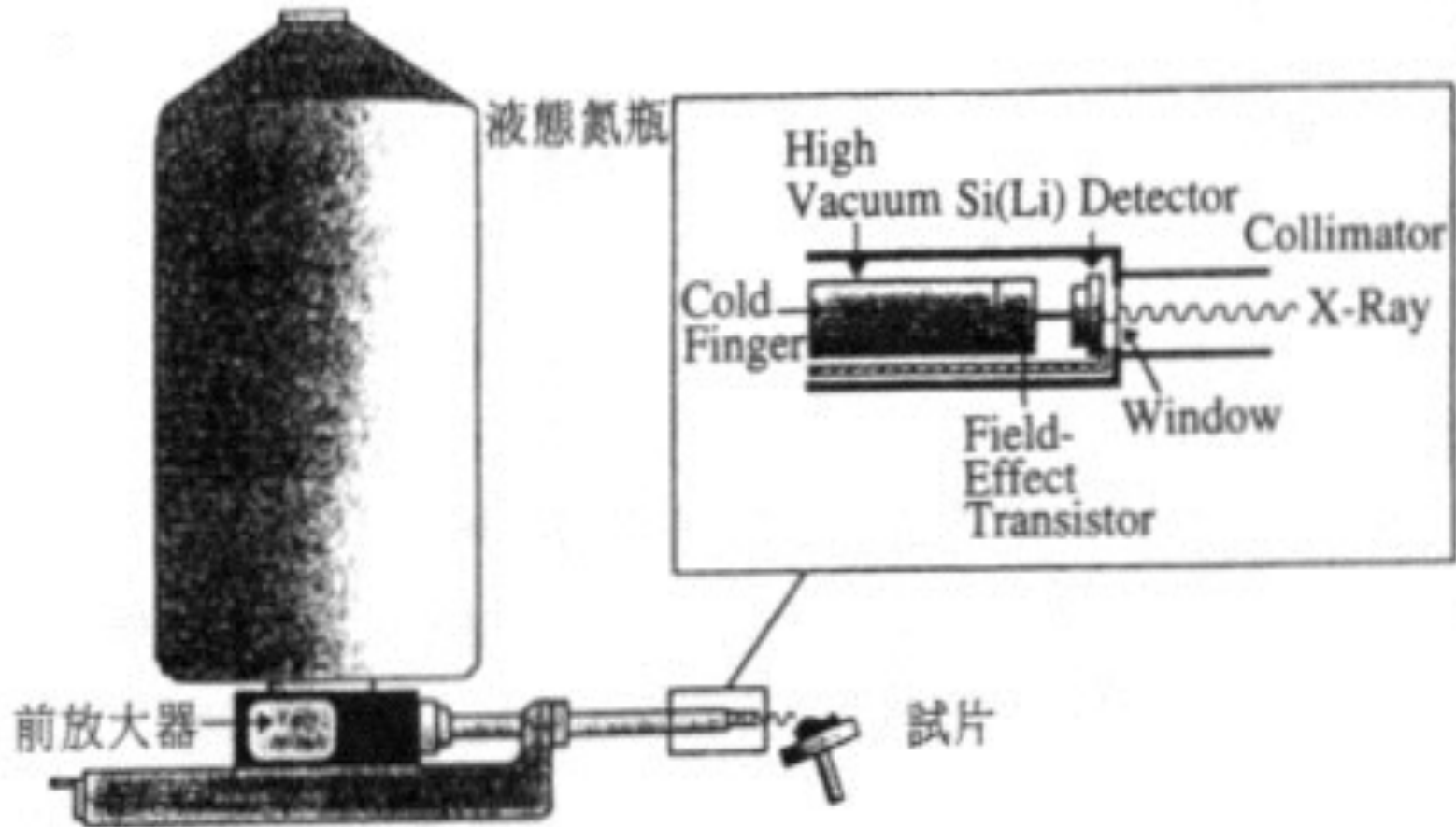


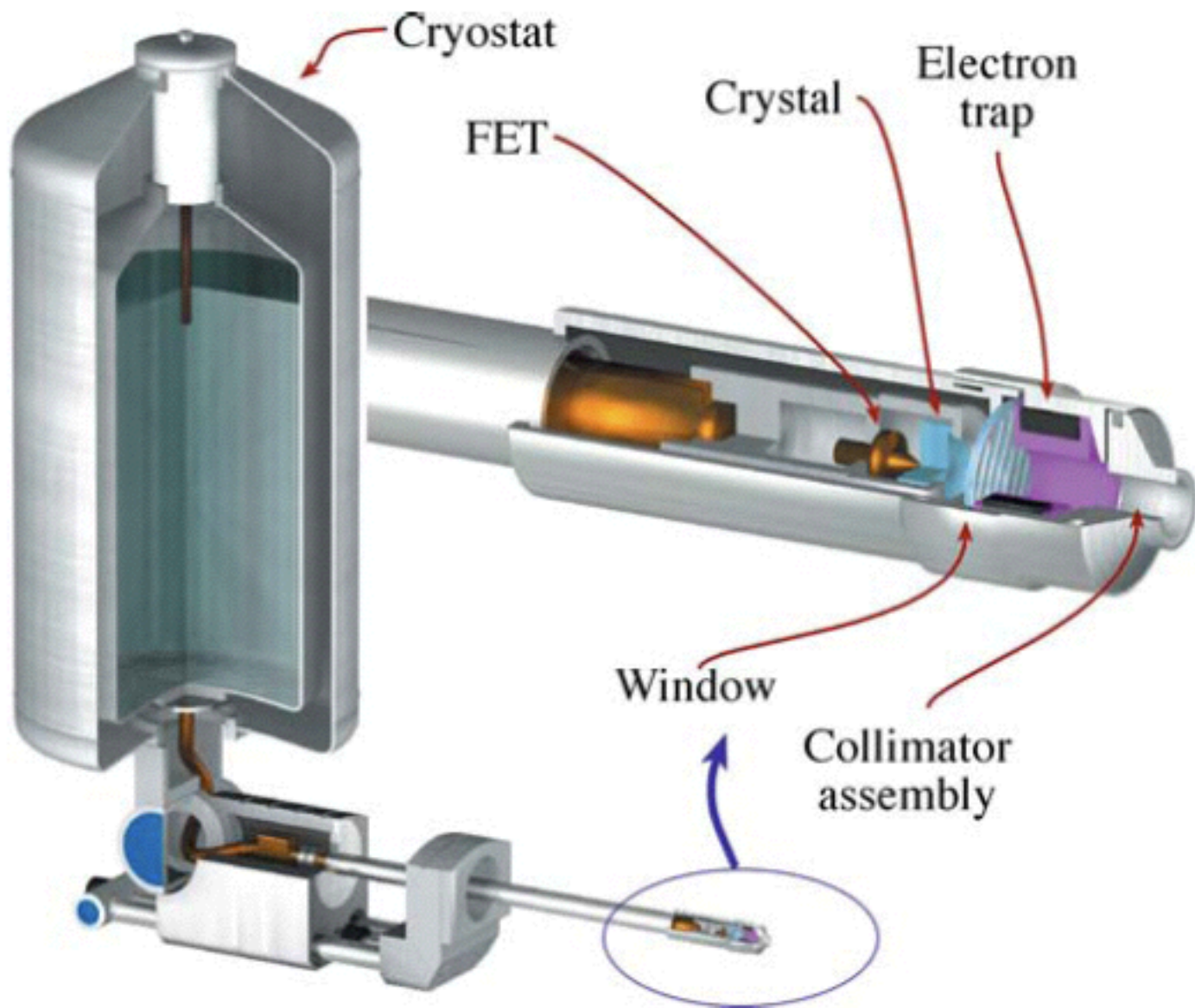


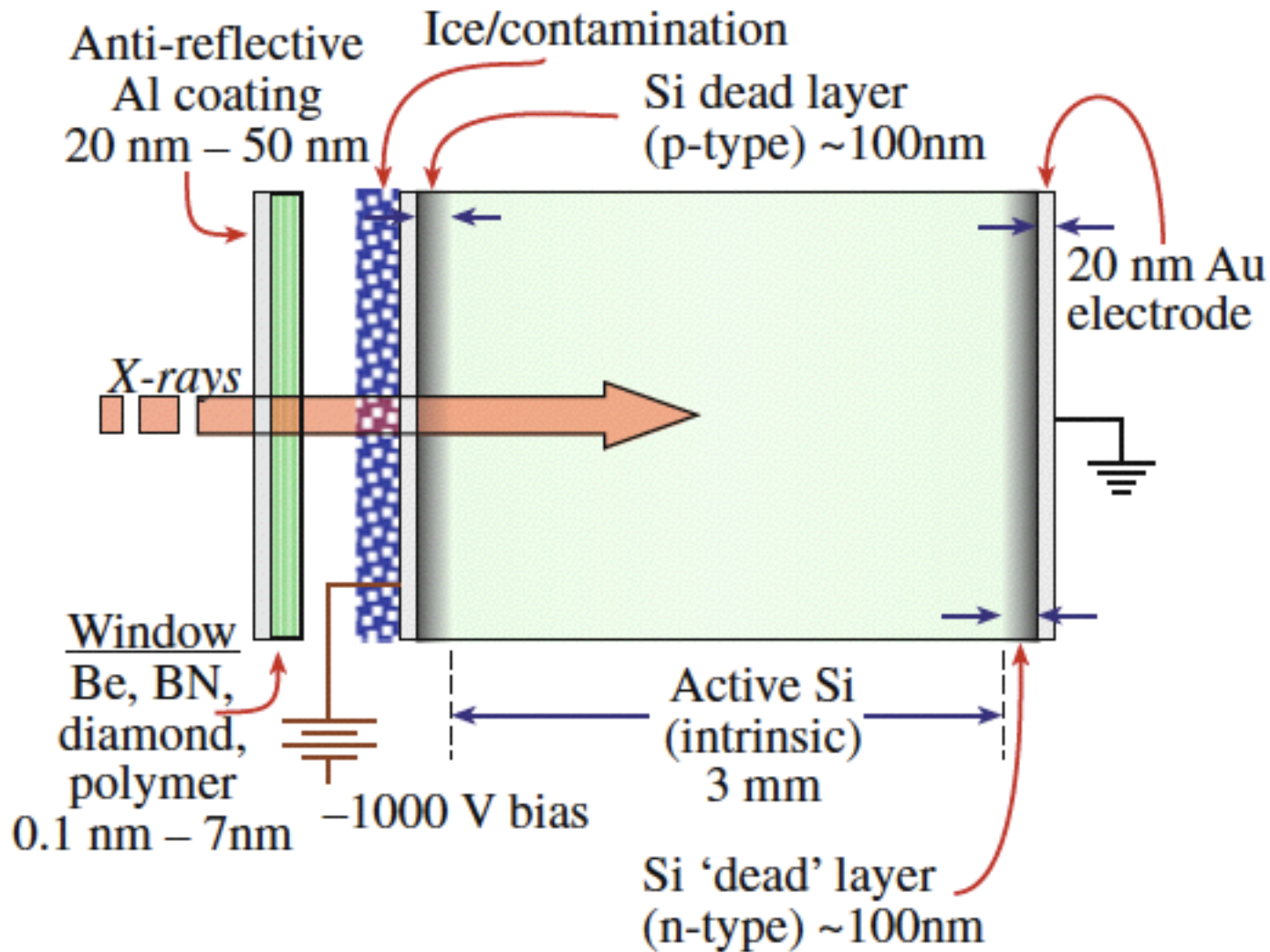
9.4.1

Semiconductor Detector

The XEDS produces spectra which are plots of X-ray counts versus X-ray energy.

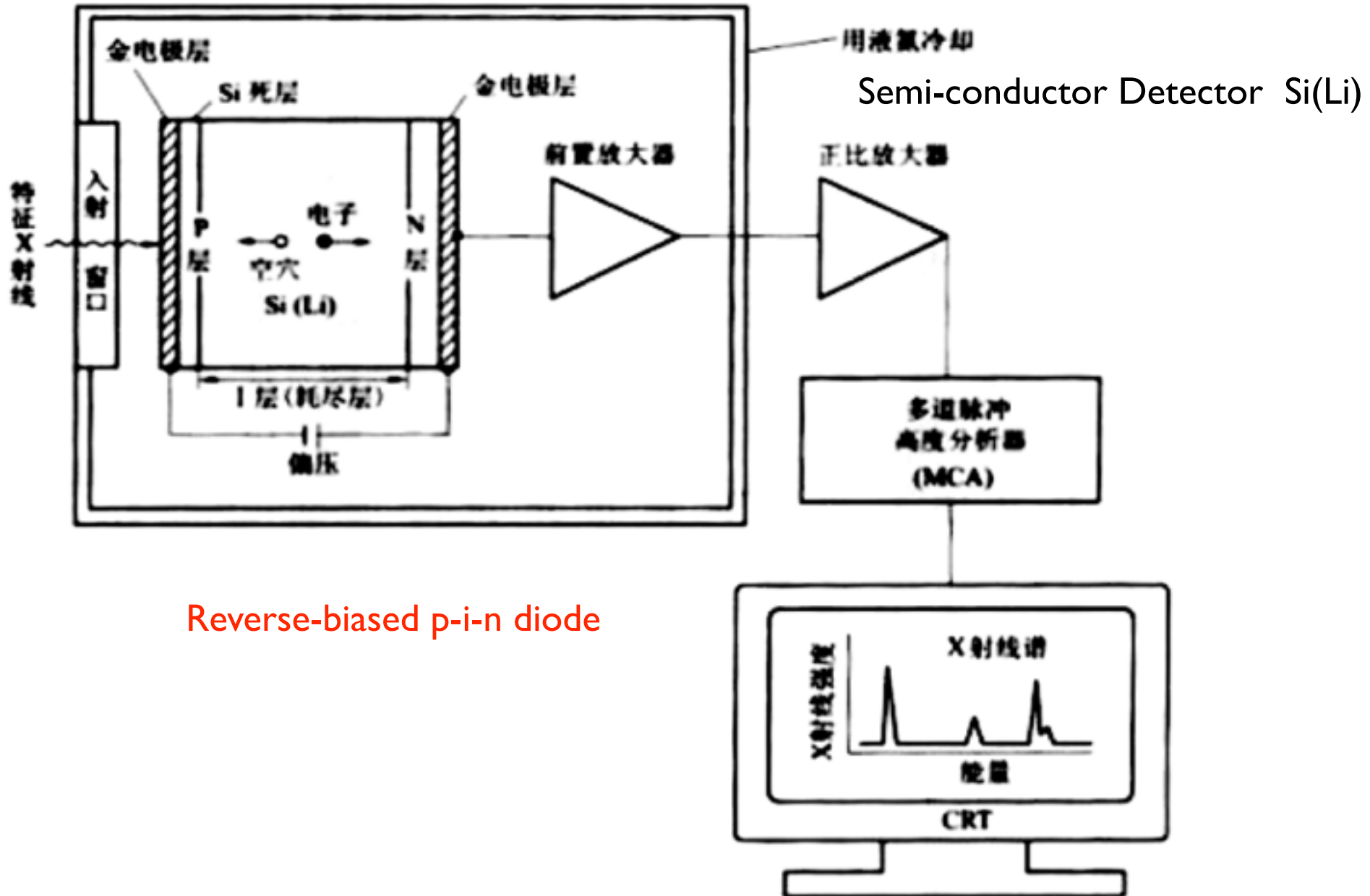






Usually, Si contains p-type impurity,
We usually compensate with Li to
create Intrinsic Si. Si(Li) is operated
under LN2 temperature to prevent
Li drift

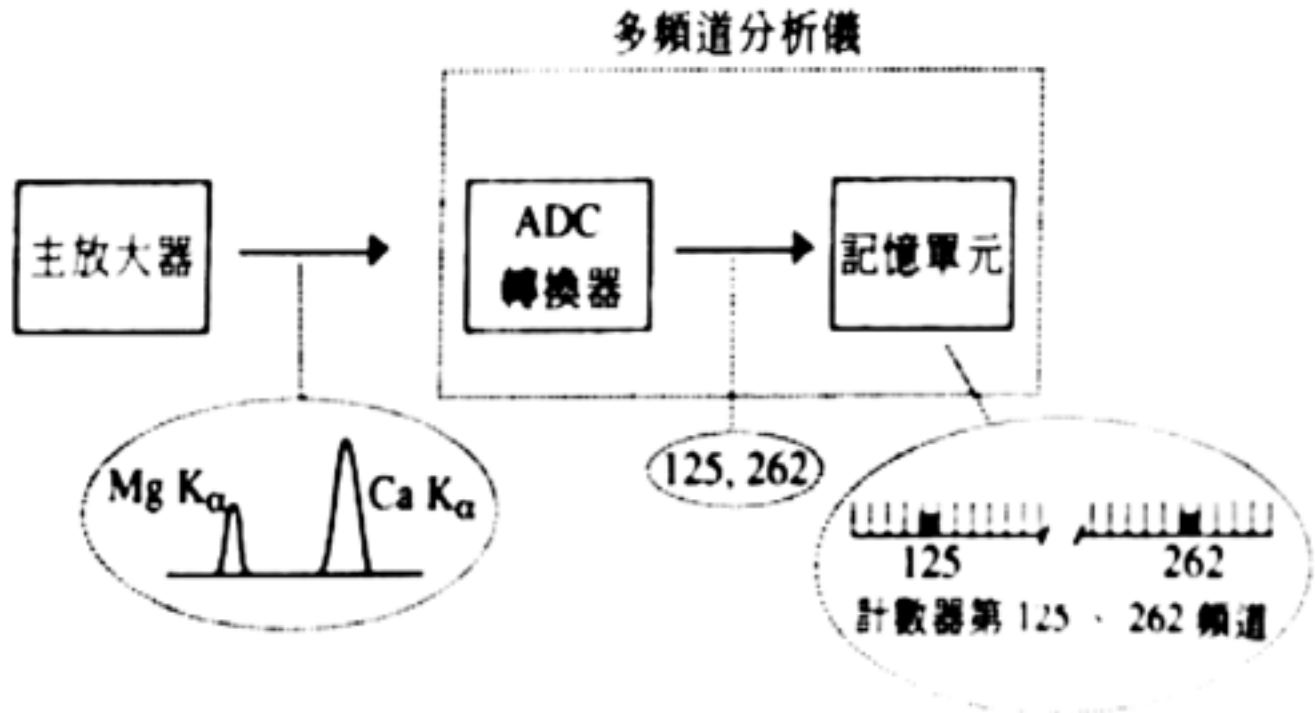
● Si(Li) detector



3.8 eV

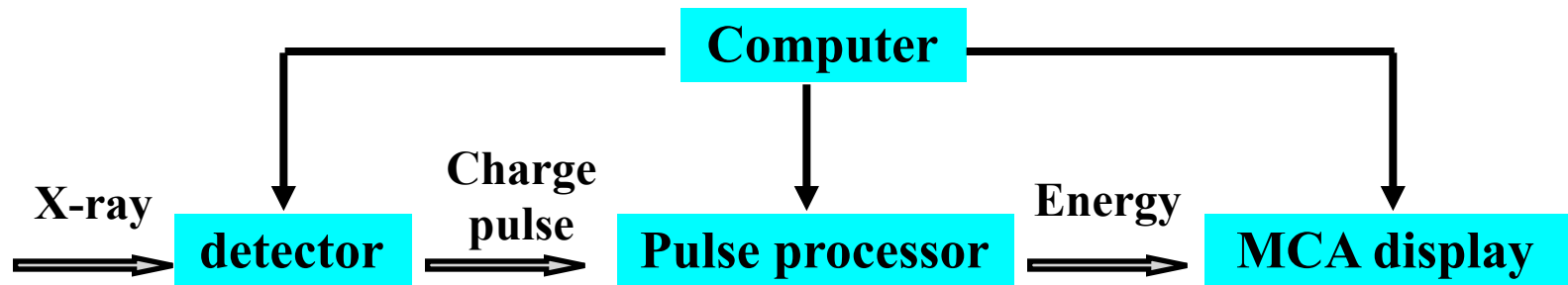
It takes ~ 3.8 eV to generate an electron-hole pair in Si, so a Be K_{α} X-ray will create at most ~ 29 electron-hole pairs, giving a charge pulse of $\sim 5 \times 10^{-18}$ C!

- (a) The energy required for the e-h transfer in Si at LN2 temperature is ~ 3.8 eV (this is not the band gap energy, but from statistical)
- (b) Characteristic X-ray has energy exceeding 1keV that is enough to generate thousands of e-h pairs
- (c) The number of e-h pair is proportional to the energy of incoming x-ray



The three main parts of the XEDS system are ...

1. detector 2. Processing electronics 3. MCA display



On/ off

MCA: *multi-channel analyzer*

(Analyze one x-ray photon at a time)

The detector generates a charge pulse proportional to the energy of X-ray

The pulse is first converted to a voltage (**detector is off**)

The signal is then amplified through a field effect transistor (FET):

detector is off

The EDX detector device

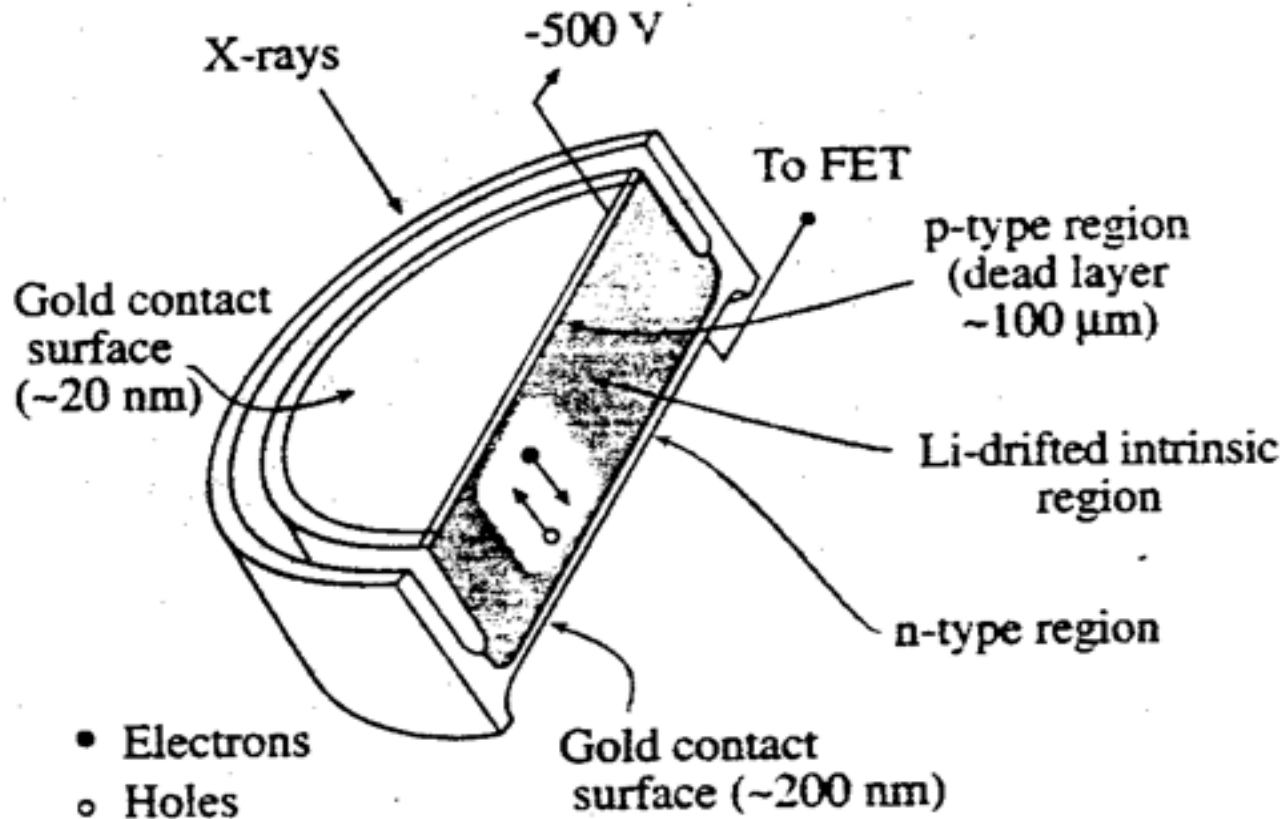
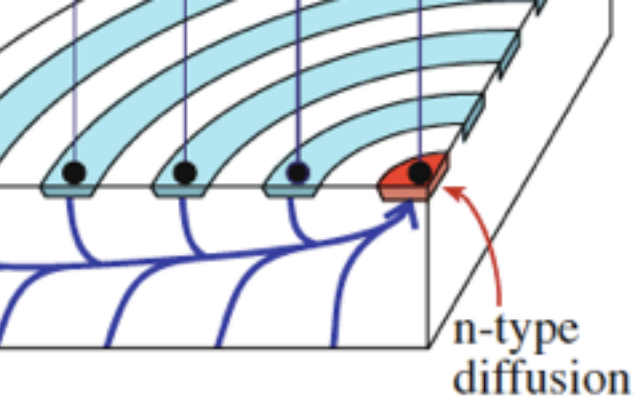


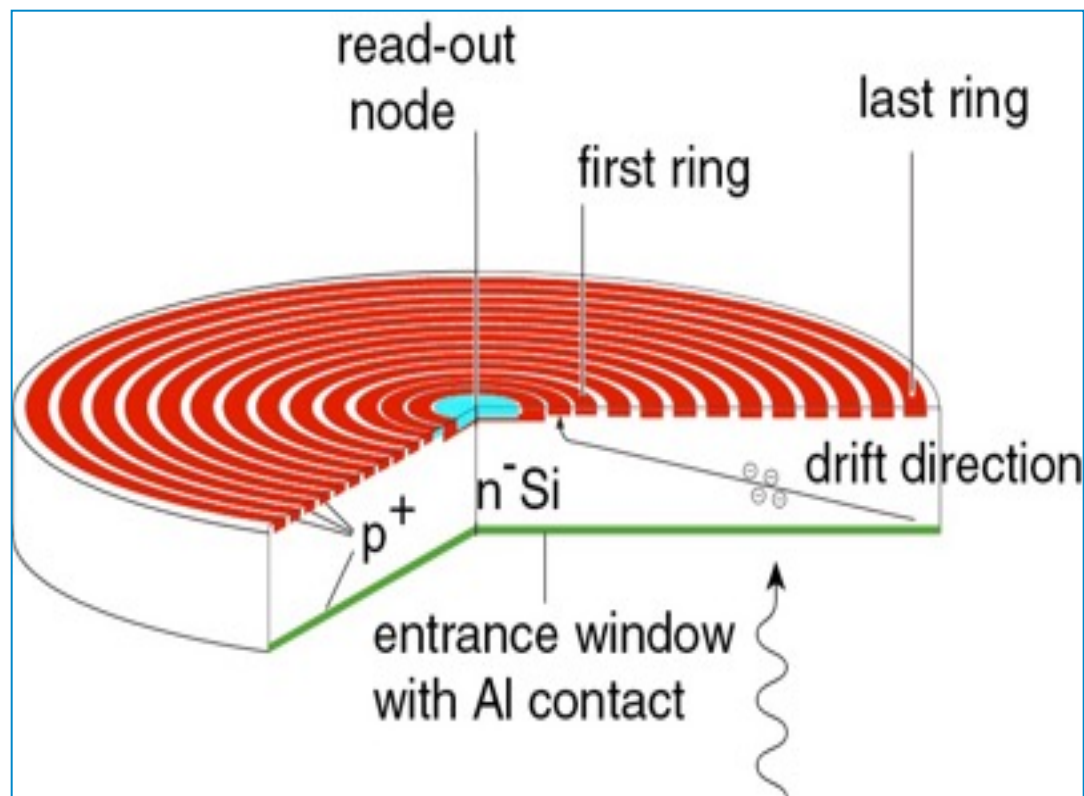
Figure 32.4. Cross section of a Si(Li) detector. The incoming X-rays generate electron-hole pairs in the intrinsic Si which are separated by an applied bias. A positive bias attracts the electrons to the rear ohmic contact after which the signal is amplified by an FET.



incident radiation
4 - 6 mm

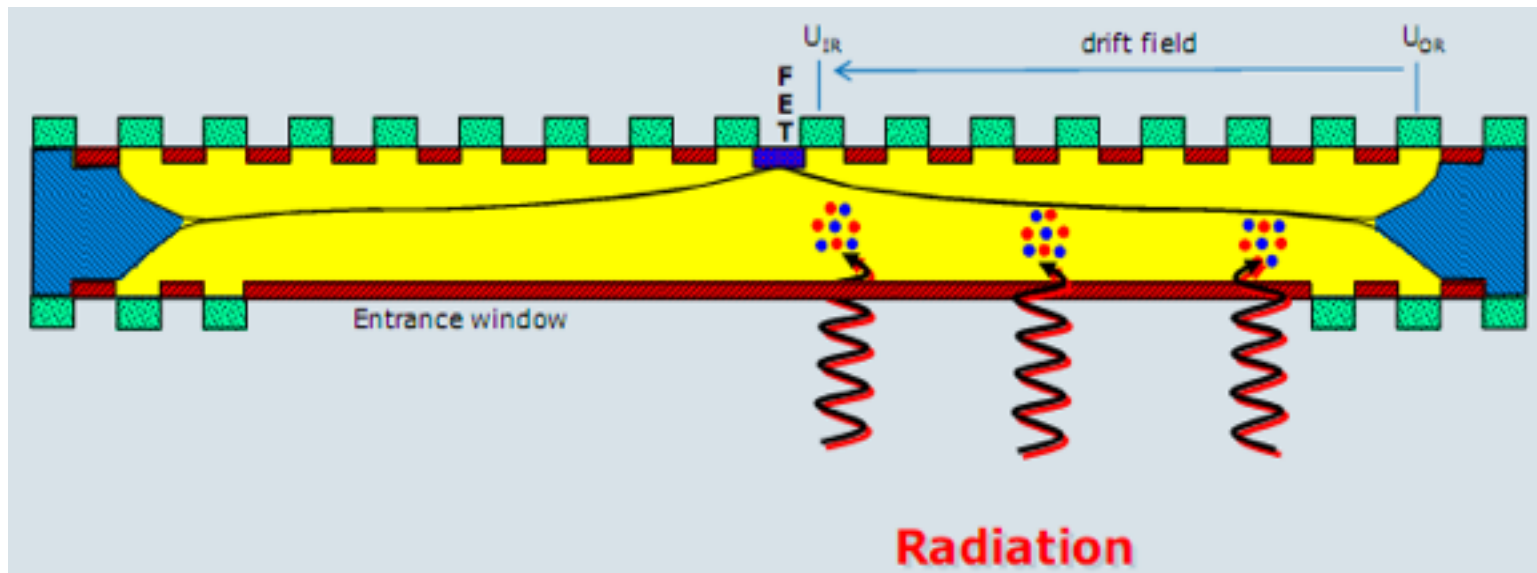
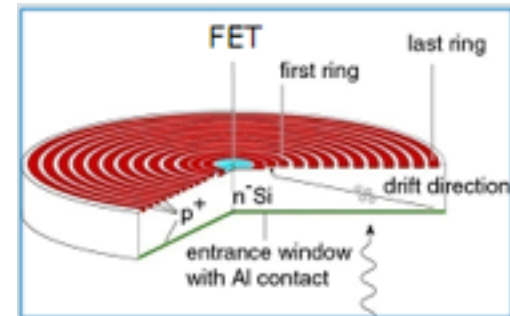
SDD

Silicon Drift Diode

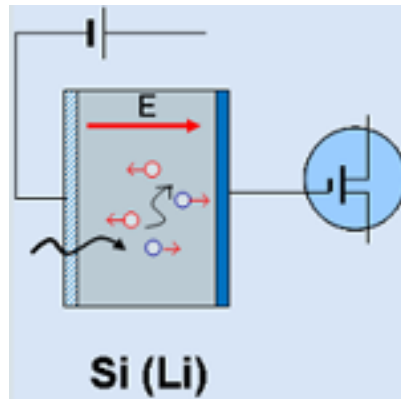


How does the SDD work?

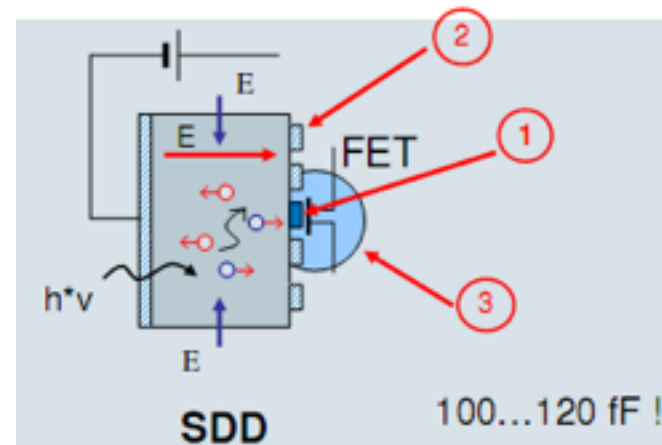
- X光打到此元件時，會產生電子雲，
- 在內環與外環加不同的電壓，形成**Drift Field**，電子雲自然會向中間電極處移動。



Si- based detector (schematic)



- Si(Li)是由整塊的Silicon去doping Li。當X光打進去時，會產生電子電洞對，電子會向陽極跑去(整個晶體的面都是陽極)，為了要減少雜訊，所以要將電極冷卻到-180度，並且是外接式的FET電晶體



- SDD是個半導體製程的元件，用半導體製程來減少陽極的面積，並且做出了drift ring，這協助電子團移動到設計的陽極處。所以可以用-20度來冷卻，也因此，可以將FET做在同一個半導體元件內。

Windows types:

- **Beryllium (Be) window detector:**

The thickness of Be is about $7\sim 12\mu\text{m}$, it is too thick to detect x-ray. The x-ray energy less than $\sim 1\text{keV}$ are strongly absorbed.

Therefore the K_{α} of $Z < 11$ can't detect. (like B, C, N and O)

- **Ultrathin window (UTW, ATW) detector:**

The thickness of UTW is usually $< 100\text{ nm}$ and the composition of polymer, diamond, boron or silicon nitride. The newer UTW like ultrathin diamond or BN or Al/polymer can withstand atmospheric pressure, termed ATWs.

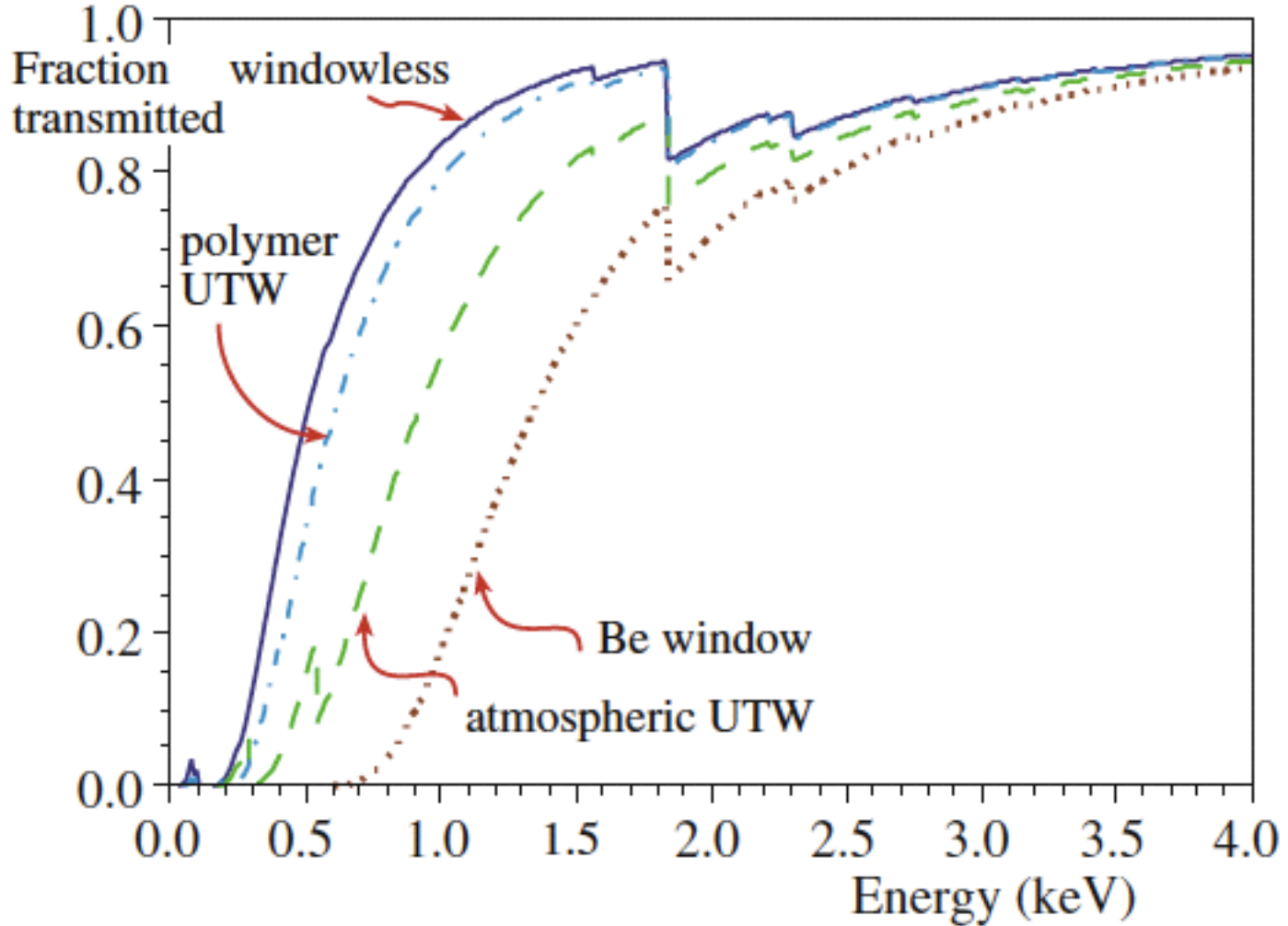
- **Windowless detector:**

This system require high vacuums, like UHV system ($\sim 10^{-8}\text{ Pa}$). The best performance of this system is the detection of Be (110 eV) K_{α}

Compare the EELS and EDX technique

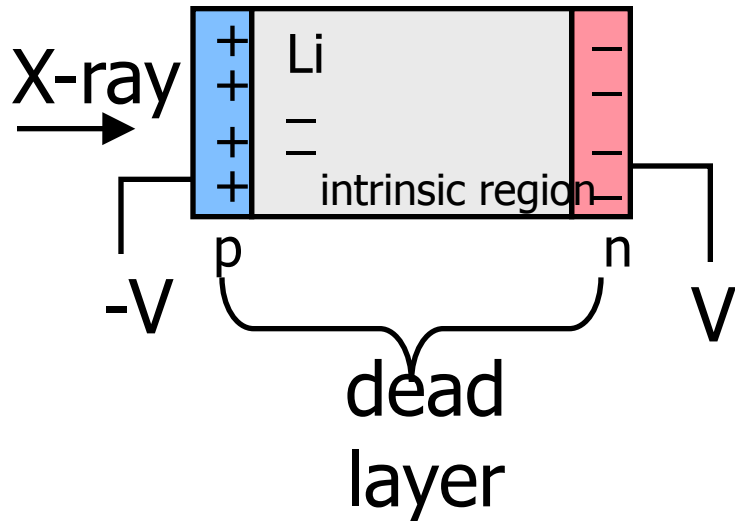
- Prior to the 1980, most EDX detector were protected (from the water vapor and hydrocarbon in the microscope column) by a 10 μ m thickness beryllium window, which strongly absorbs photons of energy less than 1000eV and precludes analysis of elements of atomic number less than 11.
- With development of ultrathin (UTW) or atmospheric-pressure (ATW), elements down to boron can be routinely detected, making EDX competitive with EELS for microanalysis of light elements in a TEM specimen.

Low energy efficiency calculated for different window types



Dead layer effect:

The p and n regions, at either of the detector, are usually termed “Dead layer”

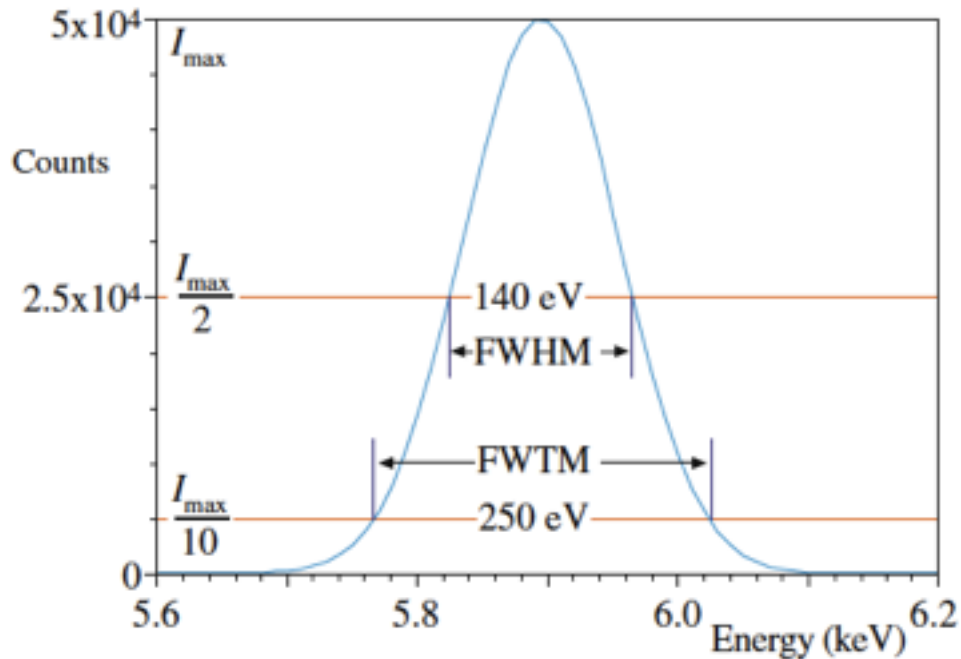


Why use Liquid N₂ cooling ?

1. Thermal energy would activate electron-hole pair, **giving a noise level.**
2. The Li atoms will diffuse under applied bias, that will **destroy the intrinsic property.**
3. The noise in FET will **mask the signal** from low-energy X-rays.

•The dead layer effect is more clearly at low-Z element.

Incomplete-charge collection (dead layer effect):



because of the dead layer, the X-ray peak will not be a perfect Gaussian shape. Usually the peak will have a low-energy tail, because some X-ray energy will be deposited in the dead layer and will not create electron-hole pairs in the intrinsic region. You can measure this ICC effect from the ratio of the full width at tenth maximum (FWTM) to the FWHM of the displayed peak,

IDEAL GAUSSIAN

An ideal Gaussian shape gives a ratio FWTM/FWHM of 1.82 (Mn K_{α} or Ni K_{α}) but this will be larger for lower-energy X-rays that are more strongly absorbed by the detector.

Intrinsic Germanium Detectors:

The higher purely intrinsic region is easier produced than Si

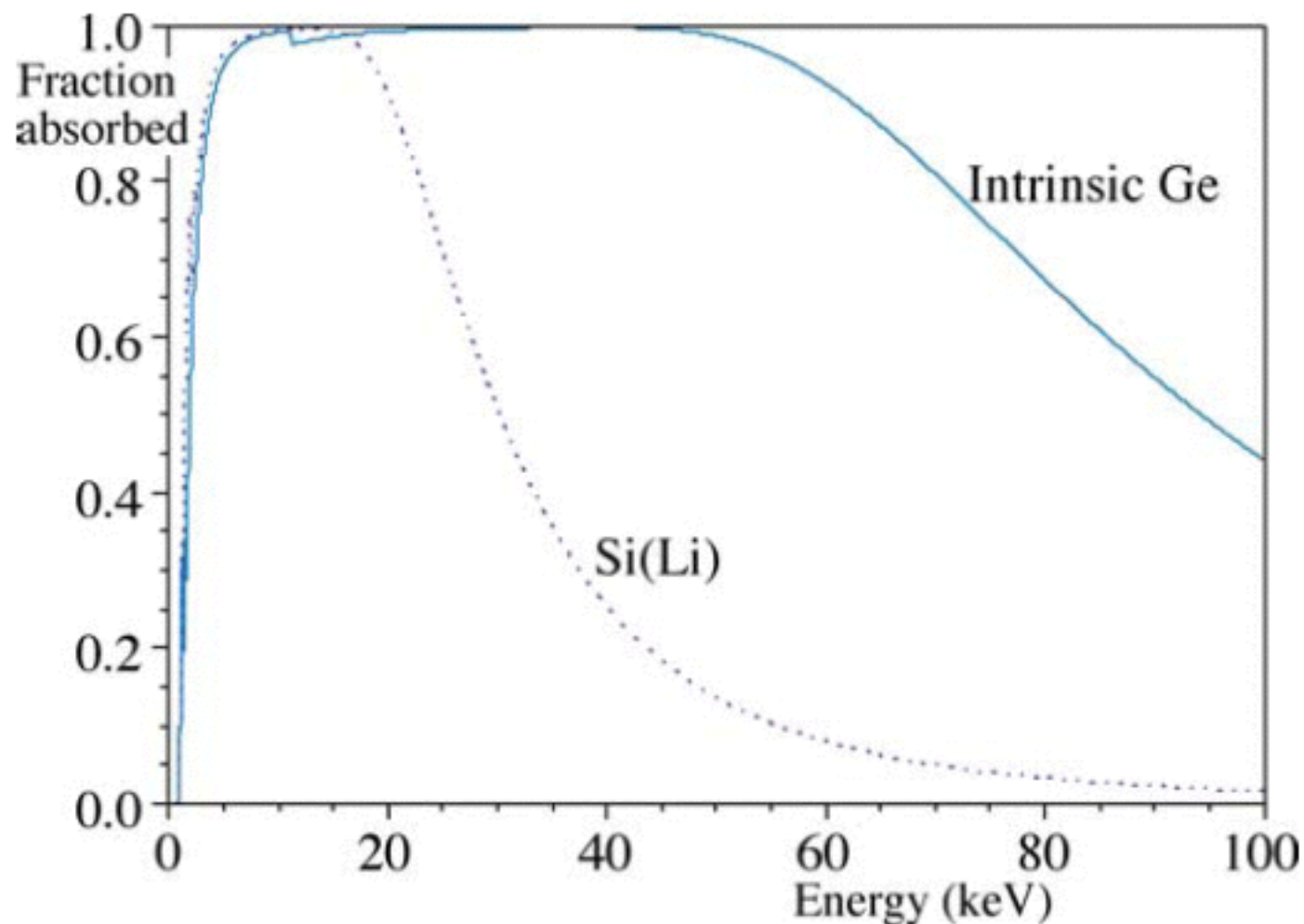
The intrinsic region (IG) is ~5 mm and can 100% efficient detect Pb $K\alpha$ ~75keV

The energy for e/h pair of IG is about 2.8 eV, smaller than Si(3.8 eV)

PROTECT YOUR DETECTOR

The intense doses of high-energy electrons or X-rays which can easily be generated in an AEM (e.g., when the beam hits a grid bar) can destroy the Li compensation in a Si(Li) detector, but there is no such problem in an IG crystal.

High energy efficiency up to 100 keV X-ray energy calculated for Si(Li) and IG dectoe



➤ A typical energy range for Si(Li) detector is 20KeV